

JV50-TR Block Diagram

Project code: 91.4FN01.001
PCB P/N : 48.4FN01.001
REVISION : 09230- -1

PCB STACKUP

TOP	_____
VCC	_____
S	_____
S	_____
GND	_____
BOTTOM	_____

SYSTEM DC/DC	
RT8205A	46
INPUTS	OUTPUTS
DCBATOUT	5V_S5 (6A)
	3D3V_S5 (6A)

SYSTEM DC/DC	
TPS51124	47
INPUTS	OUTPUTS
DCBATOUT	1D1V_S0 (7.5A)
	1D2V_S0 (4A)

SYSTEM DC/DC	
TPS51125	48
INPUTS	OUTPUTS
DCBATOUT	1D8V_S3 (11A)

RT9025	49
5V_S5	1D1V_M92

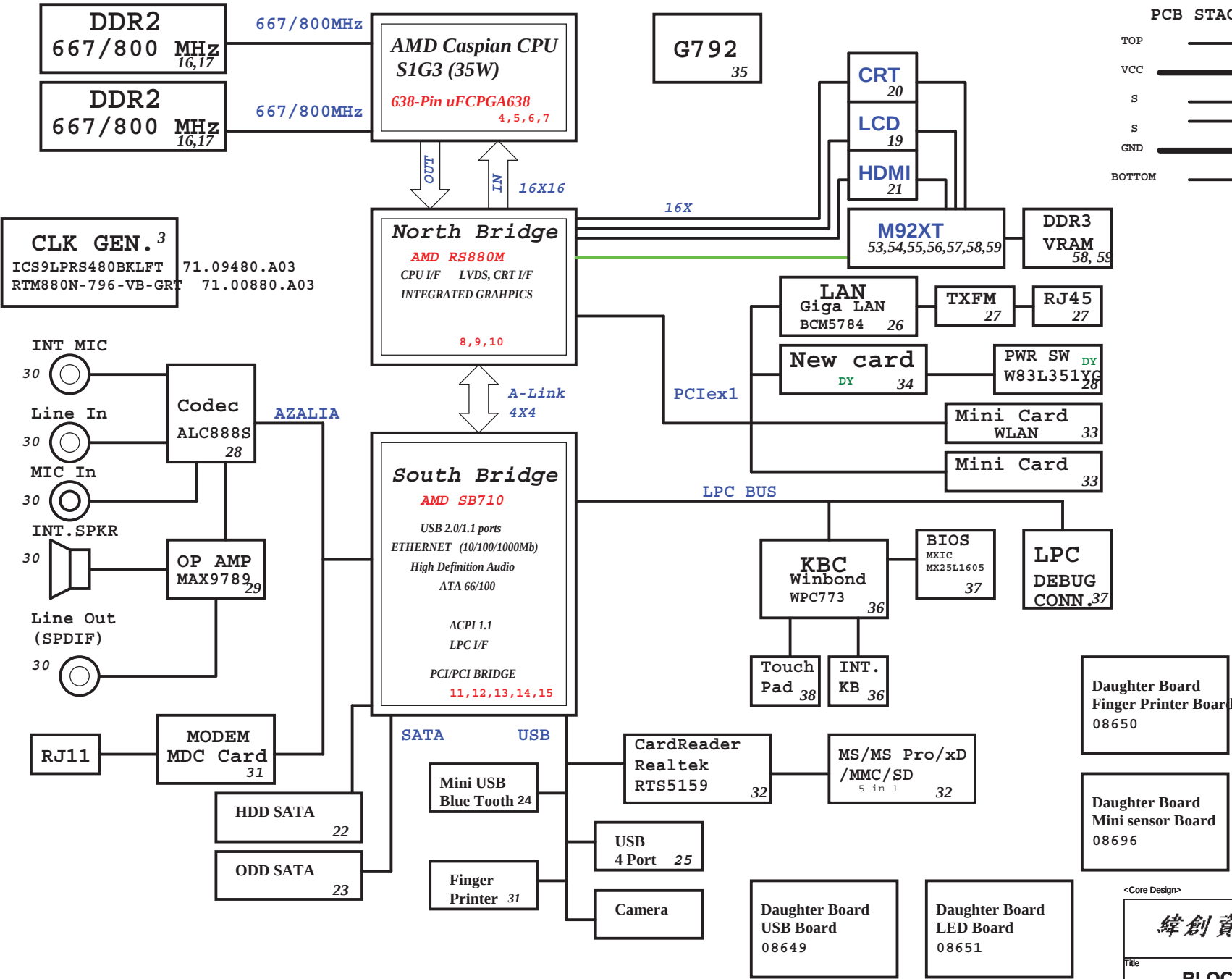
RT9161	49
3D3V_S0	2D5V_S0 (200mA)

G957	49
3D3V_S0	1D5V_S0 (1A)

G9161	49
3D3V_S5	1D2V_S5 (400mA)

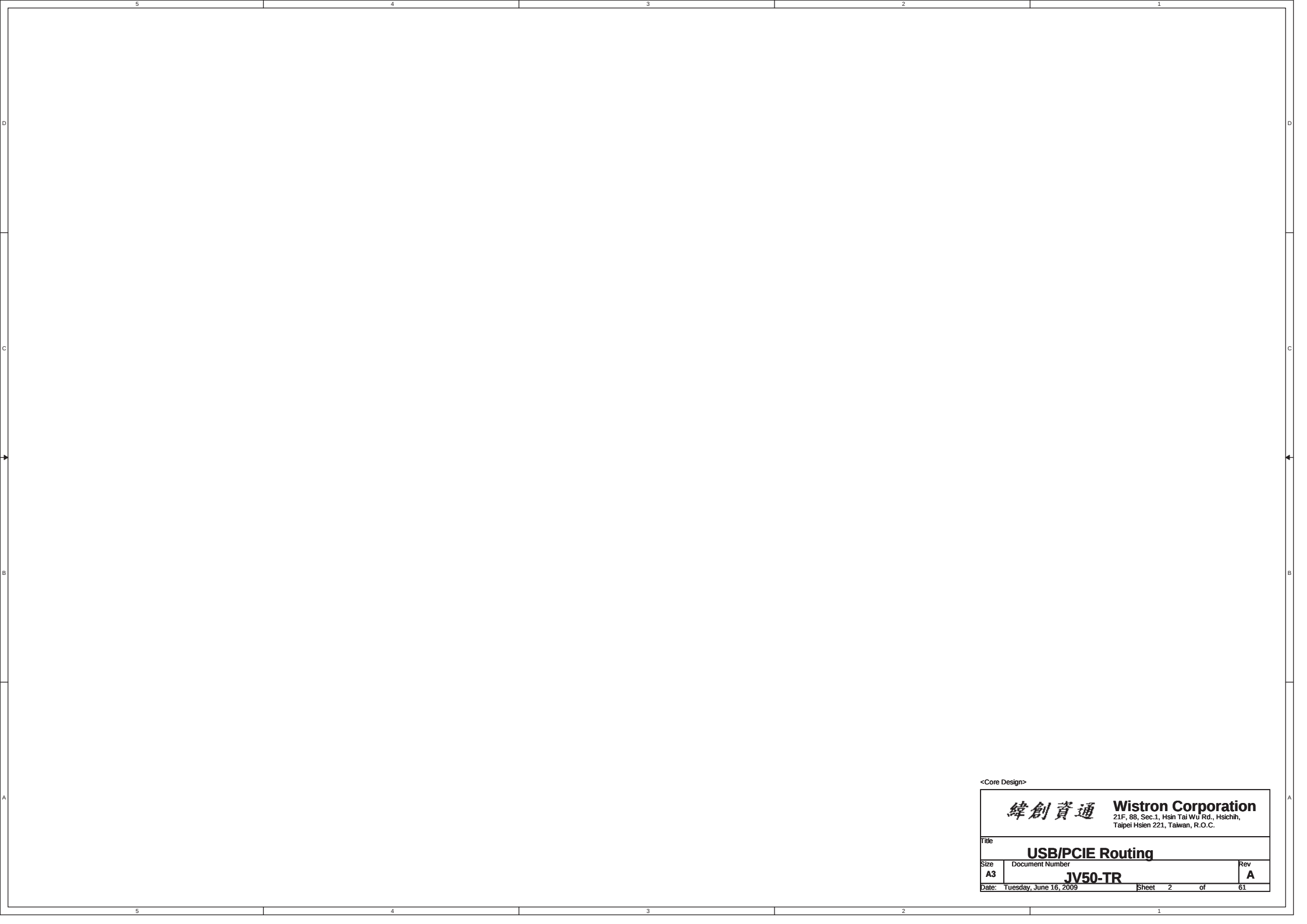
CHARGER	
MAX8731	50
INPUTS	OUTPUTS
DCBATOUT	CHG_PWR 18V 6.0A
	UP+5V 5V 100mA

CPU DC/DC	
ISL6265AHR	45
INPUTS	OUTPUTS
DCBATOUT	VCC_CORE_S0_0 0~1.55V 18A
	VCC_CORE_S0_1 0~1.55V 18A
	VDDNB 0~1.55V 18A



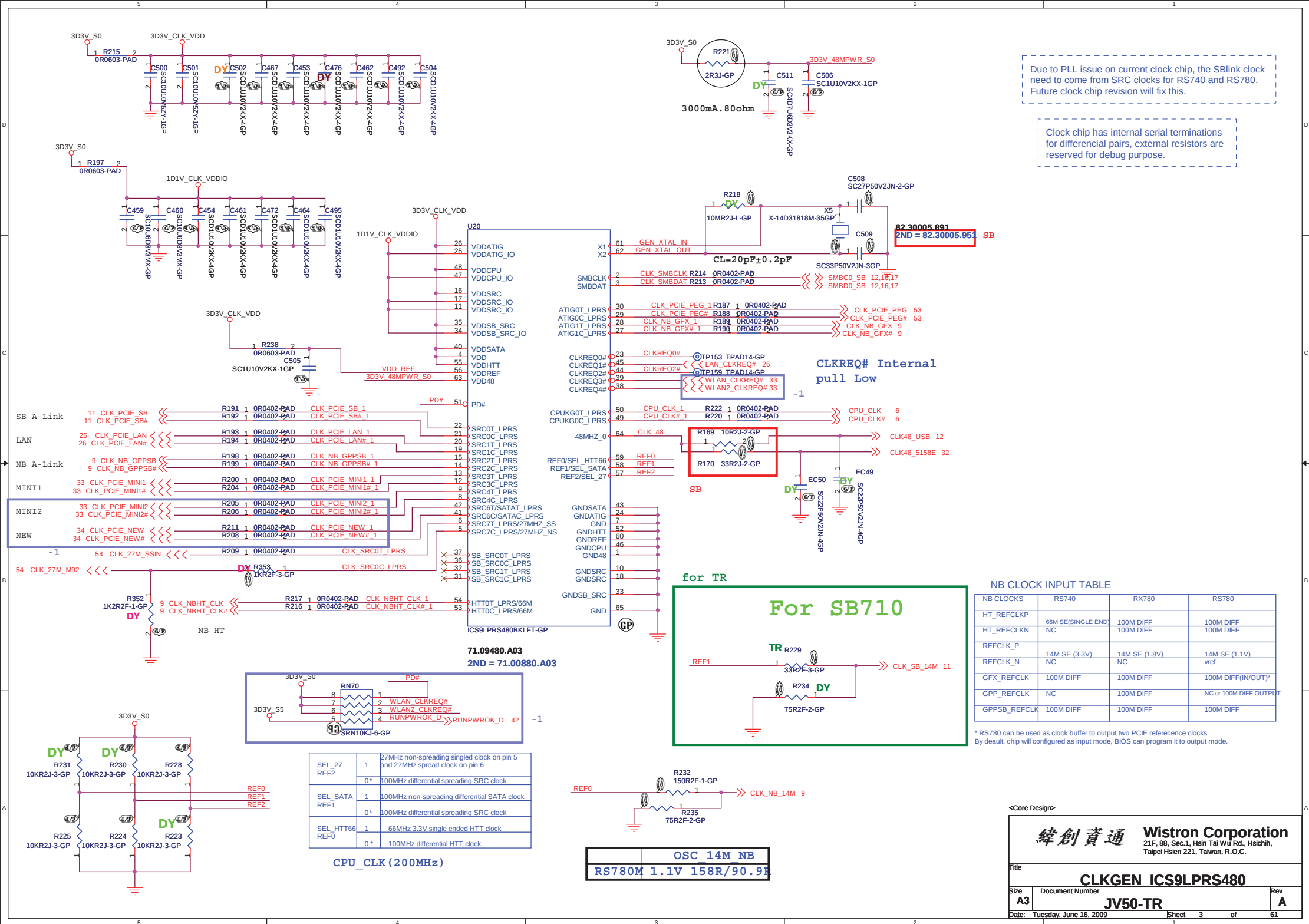
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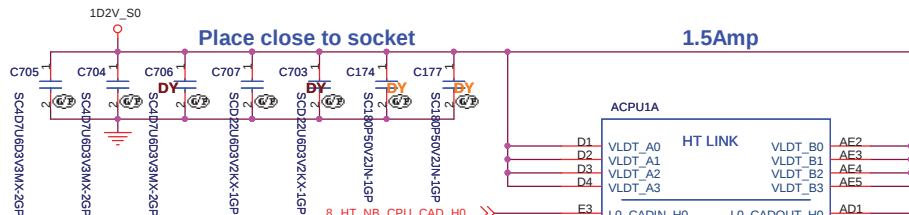
緯創資通 Wistron Corporation	
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title	
BLOCK DIAGRAM	
Size	Document Number
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<Core Design>

		Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title			
USB/PCIE Routing			
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State	Specification	Notes	ZM200100M2303
S0.C0.Px	Tcase Max	3	TBD
	NB COF	1	400 MHz
	VID_VDDNB Min	2	0.950 V
	VID_VDDNB Max	2	0.950 V
	Startup P-state		S0.C0.P7
S0.C0.P0	CPU COF	1	2000 MHz
	TDP	3	TBD
	VID_VDD Min	2	1.100 V
	VID_VDD Max	2	1.125 V
	IDD Max	3	TBD
S0.C0.P1	CPU COF	1	1800 MHz
	TDP	3	TBD
	VID_VDD Min	2	1.100 V
	VID_VDD Max	2	1.125 V
	CPU COF	1	1500 MHz
S0.C0.P2	TDP	3	TBD
	VID_VDD Min	2	1.100 V
	VID_VDD Max	2	1.125 V
	CPU COF	1	1300 MHz
	TDP	3	TBD
S0.C0.P3	VID_VDD Min	2	1.100 V
	VID_VDD Max	2	1.125 V
	CPU COF	1	1000 MHz
	TDP	3	TBD
	VID_VDD Min	2	1.100 V
S0.C0.P4	VID_VDD Max	2	1.125 V
	CPU COF	1	800 MHz
	TDP	3	TBD
	VID_VDD Min	2	1.100 V
	VID_VDD Max	2	1.125 V
S0.C0.P5	CPU COF	1	500 MHz
	TDP	3	TBD
	VID_VDD Min	2	1.100 V
	VID_VDD Max	2	1.125 V
	CPU COF	1	300 MHz
S0.C0.P6	TDP	3	TBD
	VID_VDD Min	2	1.100 V
	VID_VDD Max	2	1.125 V
	CPU COF	1	300 MHz
	TDP	3	TBD
S0.C0.P7	VID_VDD Min	2	1.100 V
	VID_VDD Max	2	1.125 V
	CPU COF	1	300 MHz
	TDP	3	TBD
	VID_VDD Min	2	1.100 V

8 HT_NB_CPU_CAD_H0
8 HT_NB_CPU_CAD_L0
8 HT_NB_CPU_CAD_H1
8 HT_NB_CPU_CAD_L1
8 HT_NB_CPU_CAD_H2
8 HT_NB_CPU_CAD_L2
8 HT_NB_CPU_CAD_H3
8 HT_NB_CPU_CAD_L3
8 HT_NB_CPU_CAD_H4
8 HT_NB_CPU_CAD_L4
8 HT_NB_CPU_CAD_H5
8 HT_NB_CPU_CAD_L5
8 HT_NB_CPU_CAD_H6
8 HT_NB_CPU_CAD_L6
8 HT_NB_CPU_CAD_H7
8 HT_NB_CPU_CAD_L7
8 HT_NB_CPU_CAD_H8
8 HT_NB_CPU_CAD_L8
8 HT_NB_CPU_CAD_H9
8 HT_NB_CPU_CAD_L9
8 HT_NB_CPU_CAD_H10
8 HT_NB_CPU_CAD_L10
8 HT_NB_CPU_CAD_H11
8 HT_NB_CPU_CAD_L11
8 HT_NB_CPU_CAD_H12
8 HT_NB_CPU_CAD_L12
8 HT_NB_CPU_CAD_H13
8 HT_NB_CPU_CAD_L13
8 HT_NB_CPU_CAD_H14
8 HT_NB_CPU_CAD_L14
8 HT_NB_CPU_CAD_H15
8 HT_NB_CPU_CAD_L15

8 HT_NB_CPU_CLK_H0
8 HT_NB_CPU_CLK_L0
8 HT_NB_CPU_CLK_H1
8 HT_NB_CPU_CLK_L1

8 HT_NB_CPU_CTL_H0
8 HT_NB_CPU_CTL_L0
8 HT_NB_CPU_CTL_H1
8 HT_NB_CPU_CTL_L1

E3 L0_CADIN_H0
E2 L0_CADIN_L0
E1 L0_CADIN_H1
F1 L0_CADIN_L1
G3 L0_CADIN_H2
G2 L0_CADIN_L2
G1 L0_CADIN_H3
H1 L0_CADIN_L3
J1 L0_CADIN_H4
K1 L0_CADIN_L4
L3 L0_CADIN_H5
L2 L0_CADIN_L5
L1 L0_CADIN_H6
M1 L0_CADIN_L6
N3 L0_CADIN_H7
N2 L0_CADIN_L7
E5 L0_CADIN_H8
E5 L0_CADIN_L8
F4 L0_CADIN_H9
G5 L0_CADIN_L9
H5 L0_CADIN_H10
H5 L0_CADIN_L10
H3 L0_CADIN_H11
H4 L0_CADIN_L11
K3 L0_CADIN_H12
K4 L0_CADIN_L12
L5 L0_CADIN_H13
M3 L0_CADIN_H14
M4 L0_CADIN_L14
N5 L0_CADIN_H15
P5 L0_CADIN_L15

J3 L0_CLKIN_H0
J2 L0_CLKIN_L0
J5 L0_CLKIN_H1
K5 L0_CLKIN_L1

N1 L0_CTLIN_H0
P1 L0_CTLIN_L0
P3 L0_CTLIN_H1
P4 L0_CTLIN_L1

SKT-CPU638P-GP-U2

62.10055.111

2ND = 62.10055.251

SKT-BGA638H176

HT LINK

D1 VLDT_A0
D2 VLDT_A1
D3 VLDT_A2
D4 VLDT_A3

L0_CADOUT_H0
L0_CADOUT_L0
L0_CADOUT_H1
L0_CADOUT_L1
L0_CADOUT_H2
L0_CADOUT_L2
L0_CADOUT_H3
L0_CADOUT_L3
L0_CADOUT_H4
L0_CADOUT_L4
L0_CADOUT_H5
L0_CADOUT_L5
L0_CADOUT_H6
L0_CADOUT_L6
L0_CADOUT_H7
L0_CADOUT_L7
L0_CADOUT_H8
L0_CADOUT_L8
L0_CADOUT_H9
L0_CADOUT_L9
L0_CADOUT_H10
L0_CADOUT_L10
L0_CADOUT_H11
L0_CADOUT_L11
L0_CADOUT_H12
L0_CADOUT_L12
L0_CADOUT_H13
L0_CADOUT_L13
L0_CADOUT_H14
L0_CADOUT_L14
L0_CADOUT_H15
L0_CADOUT_L15

L0_CLKOUT_H0
L0_CLKOUT_L0
L0_CLKOUT_H1
L0_CLKOUT_L1

L0_CTLOUT_H0
L0_CTLOUT_L0
L0_CTLOUT_H1
L0_CTLOUT_L1

VLDT_B0
VLDT_B1
VLDT_B2
VLDT_B3

AD1
AC1
AC2
AC3
AB1
AA1
AA2
AA3
W2
W3
V1
U1
U2
U3
T1
R1
AD4
AD3
AD5
AC5
AB4
AB3
AB5
AA5
W5
W4
V3
V5
U5
T4
T3

Y1
W1
Y4
Y3

R2
R3
T5
R5

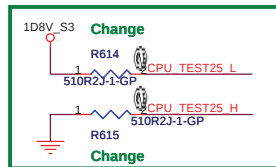
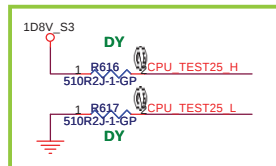
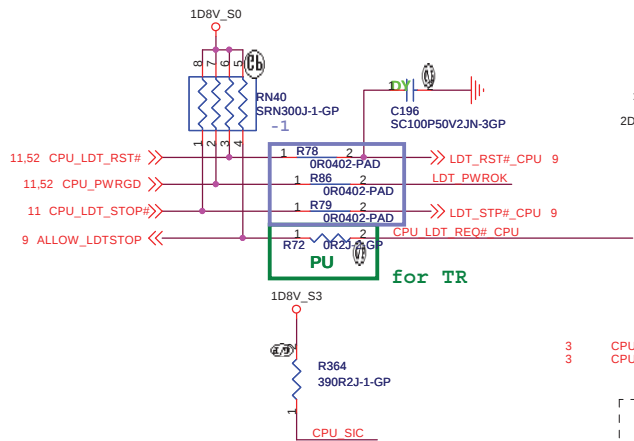
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HT_CPU_NB_CAD_L0 8
HT_CPU_NB_CAD_H1 8
HT_CPU_NB_CAD_L1 8
HT_CPU_NB_CAD_H2 8
HT_CPU_NB_CAD_L2 8
HT_CPU_NB_CAD_H3 8
HT_CPU_NB_CAD_L3 8
HT_CPU_NB_CAD_H4 8
HT_CPU_NB_CAD_L4 8
HT_CPU_NB_CAD_H5 8
HT_CPU_NB_CAD_L5 8
HT_CPU_NB_CAD_H6 8
HT_CPU_NB_CAD_L6 8
HT_CPU_NB_CAD_H7 8
HT_CPU_NB_CAD_L7 8
HT_CPU_NB_CAD_H8 8
HT_CPU_NB_CAD_L8 8
HT_CPU_NB_CAD_H9 8
HT_CPU_NB_CAD_L9 8
HT_CPU_NB_CAD_H10 8
HT_CPU_NB_CAD_L10 8
HT_CPU_NB_CAD_H11 8
HT_CPU_NB_CAD_L11 8
HT_CPU_NB_CAD_H12 8
HT_CPU_NB_CAD_L12 8
HT_CPU_NB_CAD_H13 8
HT_CPU_NB_CAD_L13 8
HT_CPU_NB_CAD_H14 8
HT_CPU_NB_CAD_L14 8
HT_CPU_NB_CAD_H15 8
HT_CPU_NB_CAD_L15 8

HT_CPU_NB_CLK_H0 8
HT_CPU_NB_CLK_L0 8
HT_CPU_NB_CLK_H1 8
HT_CPU_NB_CLK_L1 8

HT_CPU_NB_CTL_H0 8
HT_CPU_NB_CTL_L0 8
HT_CPU_NB_CTL_H1 8
HT_CPU_NB_CTL_L1 8

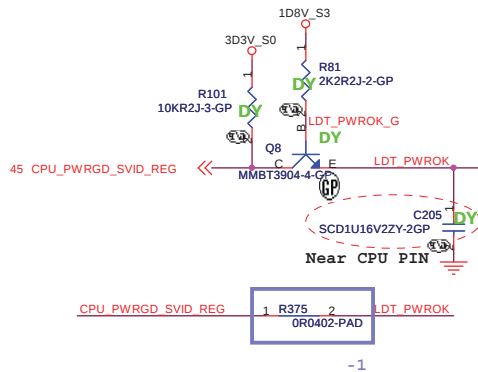
<Core Design>

緯創資通 Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.		
Title CPU HT LINK I/F (1/4)		
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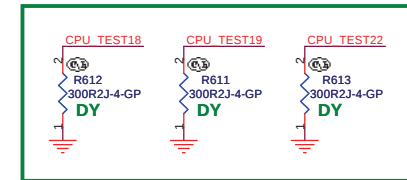
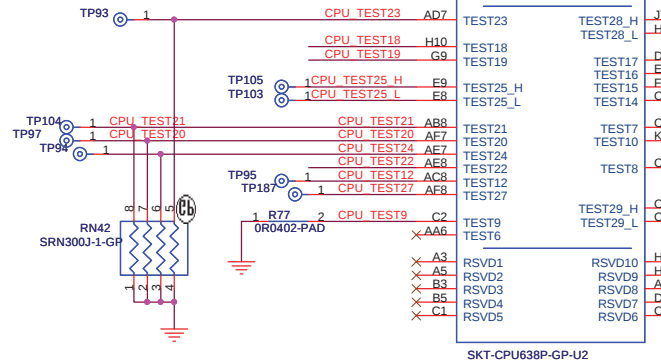
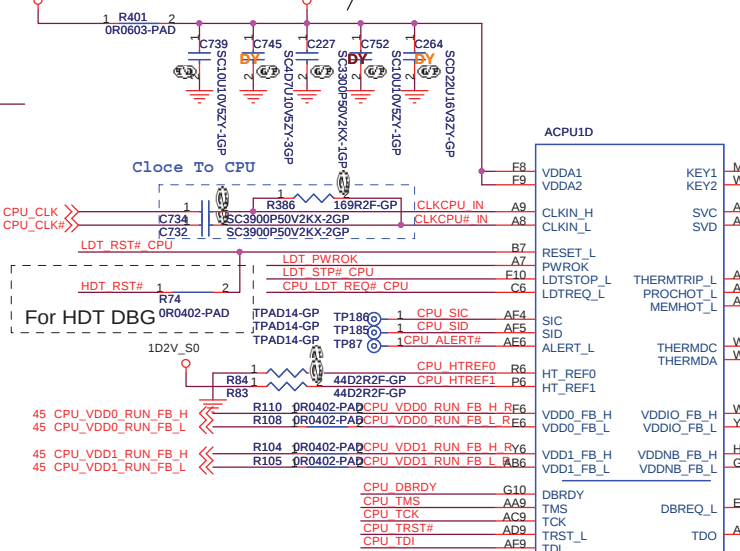
for TR

PU-->300R
TR-->510R



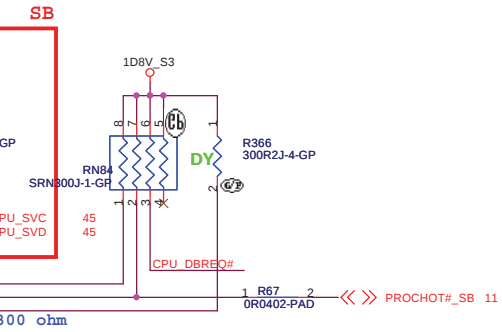
Near CPU PIN

IF 0 ohm IS NOT GOOD ENOUGH, TRY 68.00082.491
LAYOUT:ROUTE VDDA TRACE APPROX.
50mils WIDE(USE 2X25 mil TRACES TO
EXIT BALL FIELD) AND 500 mils LONG.

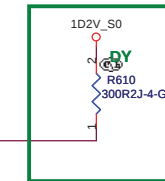


CPU exceeds to 125°C

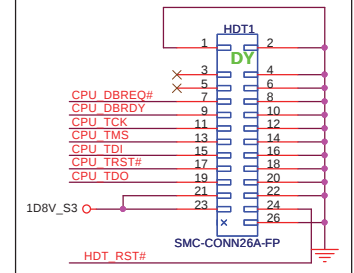
The Processor has
reached a preset
maximum operating
temperature. 100°C
I=Active HTC
O=FAN



LAYOUT: Route FBCLKOUT_H/L
differentially impedance 80



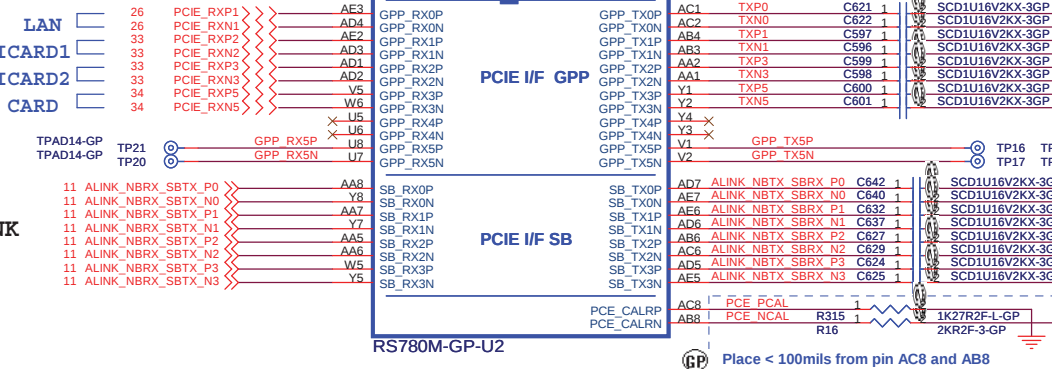
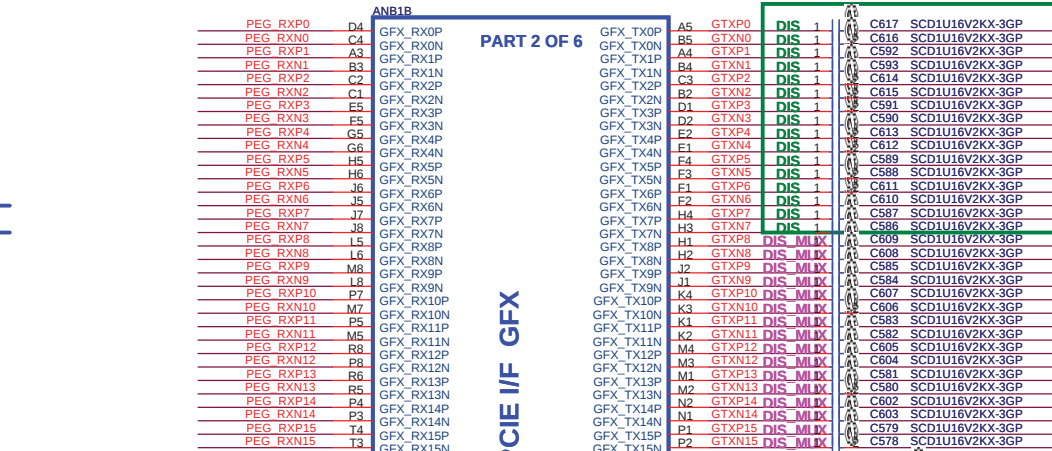
HDT Connectors



<Core Design>

緯創資通 Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

CPU_Control&Debug_(3/4)			
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PEG_TXP[15.0] 53
PEG_TXN[15.0] 53

RS780M Display Port Support (muxed on GFX)

DP0	GFX_TX0, TX1, TX2, TX3, AUX0, HPD0
DP1	GFX_TX4, TX5, TX6, TX7, AUX1, HPD1

GTXP0	UMA_MUX	C30	1	SCD1U16V2KX-3GP	PEG_TXP0	HDMI_DATA2+	21
GTXP1	UMA_MUX	C29	1	SCD1U16V2KX-3GP	PEG_TXN0	HDMI_DATA2-	21
GTXP2	UMA_MUX	C28	1	SCD1U16V2KX-3GP	PEG_TXP1	HDMI_DATA1+	21
GTXP3	UMA_MUX	C27	1	SCD1U16V2KX-3GP	PEG_TXN1	HDMI_DATA1-	21
GTXP4	UMA_MUX	C26	1	SCD1U16V2KX-3GP	PEG_TXP2	HDMI_DATA0+	21
GTXP5	UMA_MUX	C25	1	SCD1U16V2KX-3GP	PEG_TXN2	HDMI_DATA0-	21
GTXP6	UMA_MUX	C24	1	SCD1U16V2KX-3GP	PEG_TXP3	HDMI_CLK+	21
GTXP7	UMA_MUX	C23	1	SCD1U16V2KX-3GP	PEG_TXN3	HDMI_CLK-	21

LAN
MINICARD1
MINICARD2
NEW CARD

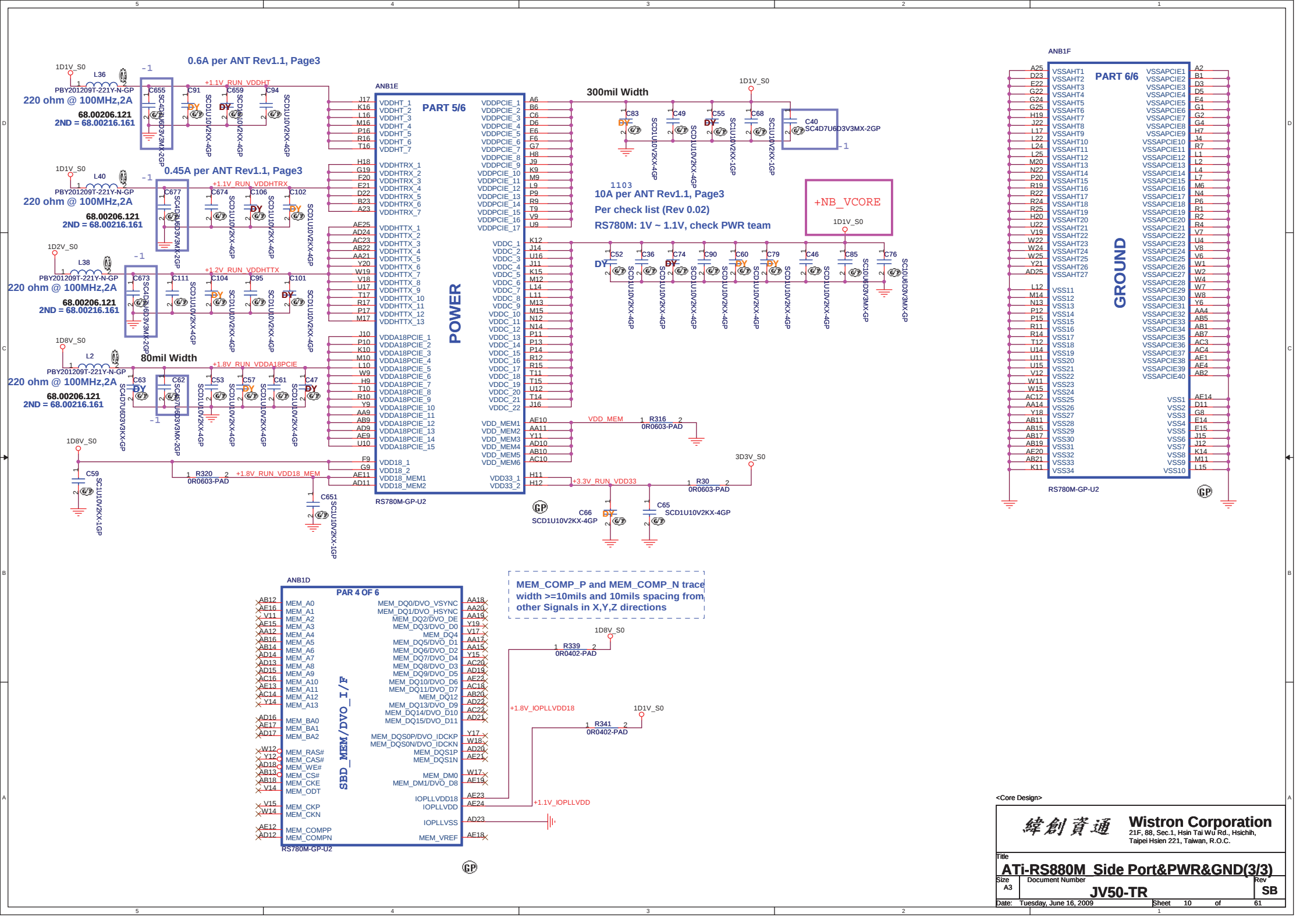
GTXP0	UMA_MUX	C30	1	SCD1U16V2KX-3GP	PEG_TXP0	HDMI_DATA2+	21
GTXP1	UMA_MUX	C29	1	SCD1U16V2KX-3GP	PEG_TXN0	HDMI_DATA2-	21
GTXP2	UMA_MUX	C28	1	SCD1U16V2KX-3GP	PEG_TXP1	HDMI_DATA1+	21
GTXP3	UMA_MUX	C27	1	SCD1U16V2KX-3GP	PEG_TXN1	HDMI_DATA1-	21
GTXP4	UMA_MUX	C26	1	SCD1U16V2KX-3GP	PEG_TXP2	HDMI_DATA0+	21
GTXP5	UMA_MUX	C25	1	SCD1U16V2KX-3GP	PEG_TXN2	HDMI_DATA0-	21
GTXP6	UMA_MUX	C24	1	SCD1U16V2KX-3GP	PEG_TXP3	HDMI_CLK+	21
GTXP7	UMA_MUX	C23	1	SCD1U16V2KX-3GP	PEG_TXN3	HDMI_CLK-	21

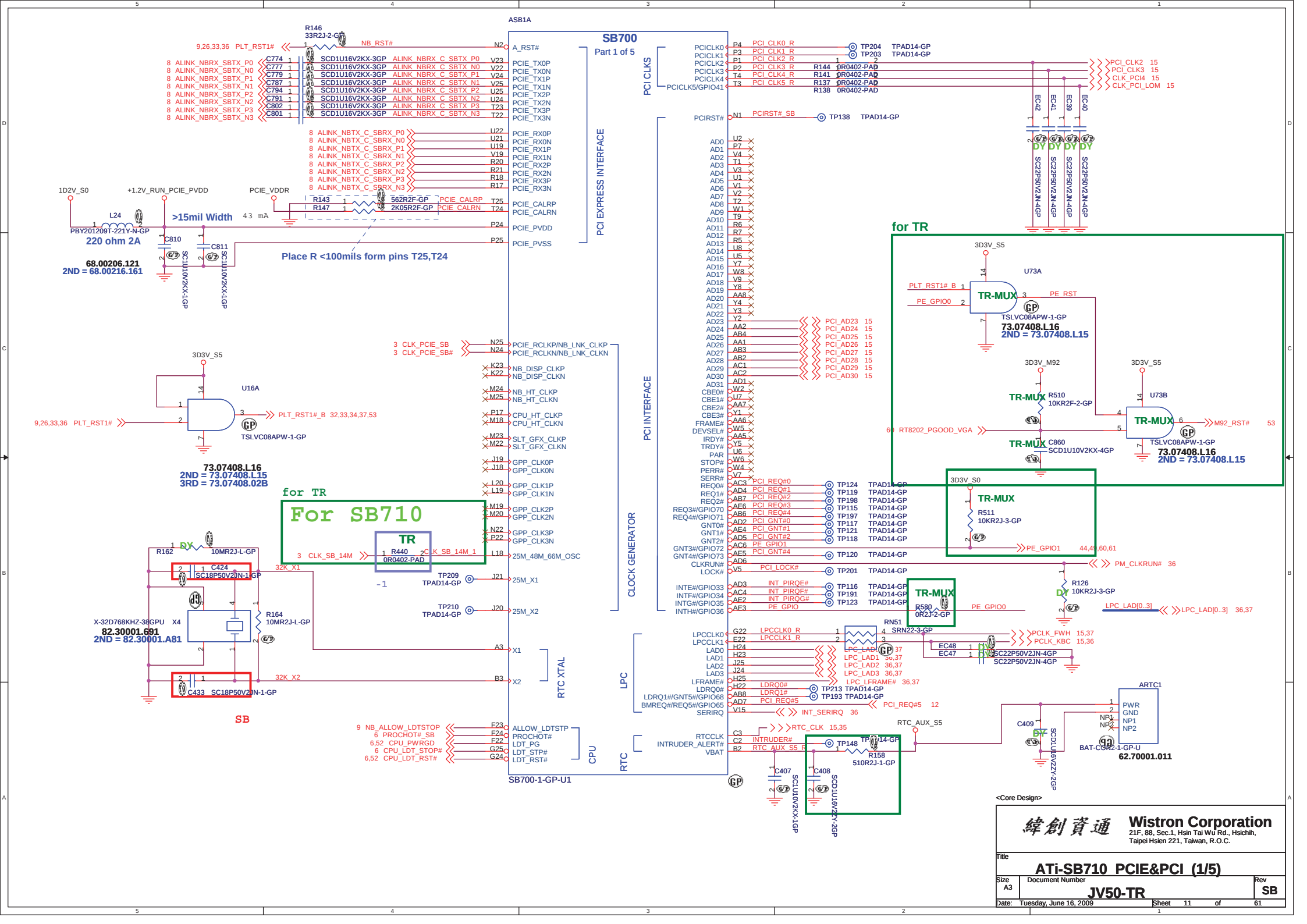
LAN
MINICARD1
MINICARD2
NEW CARD

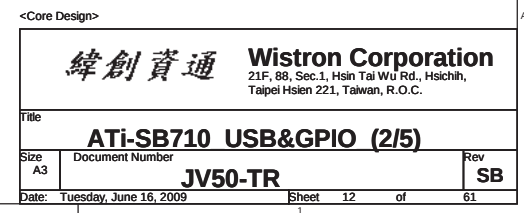
ATi-RS880M_HT LINK&PCIe(1/3)

Size A3
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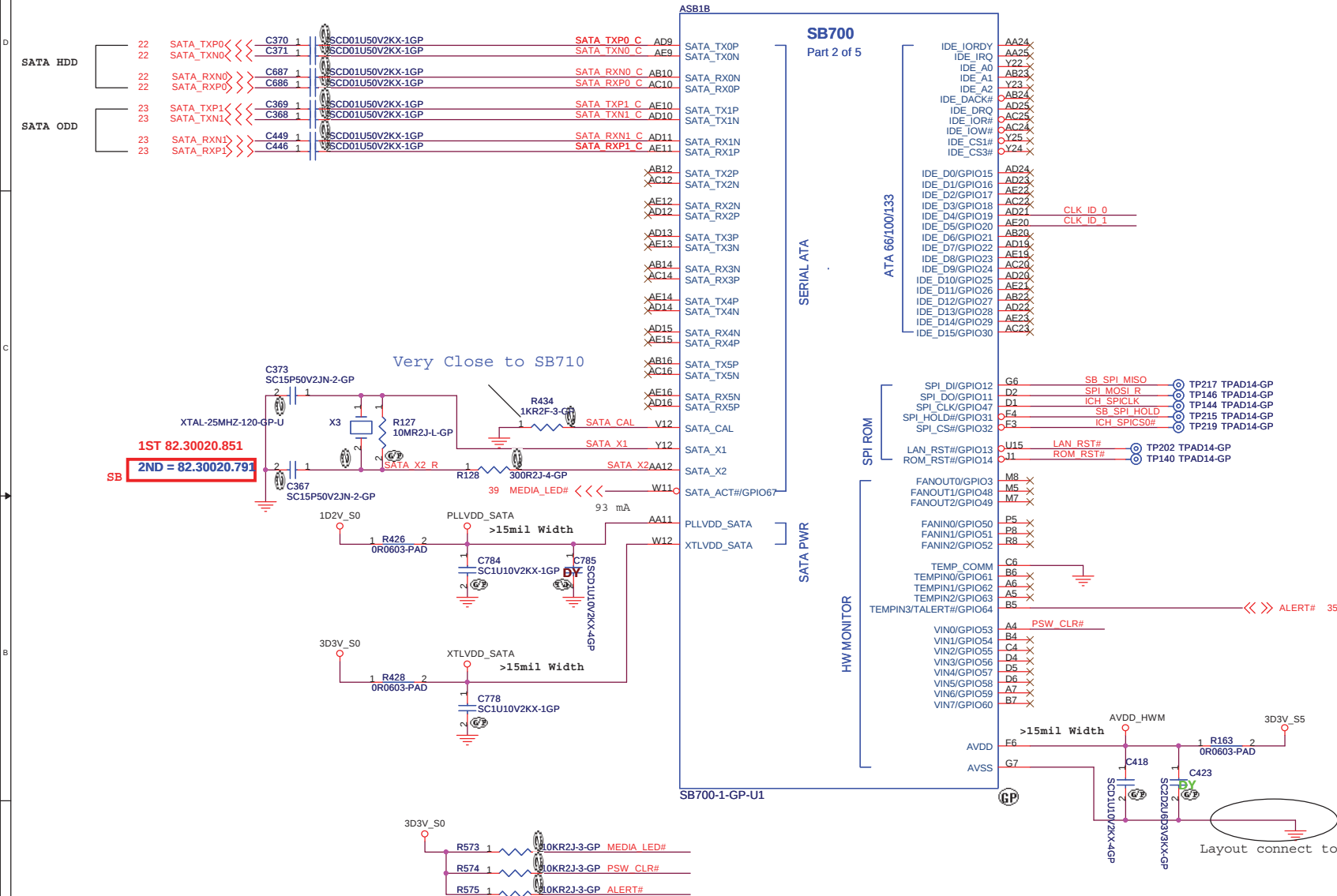




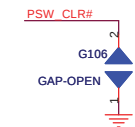
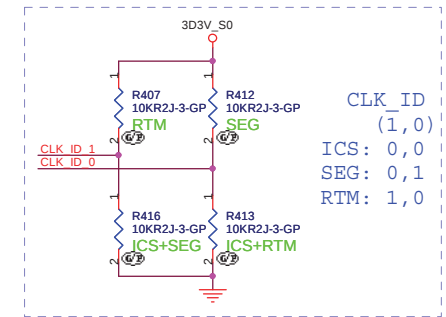




PLACE SATA AC DECOUPLING
CAPS CLOSE TO SB710

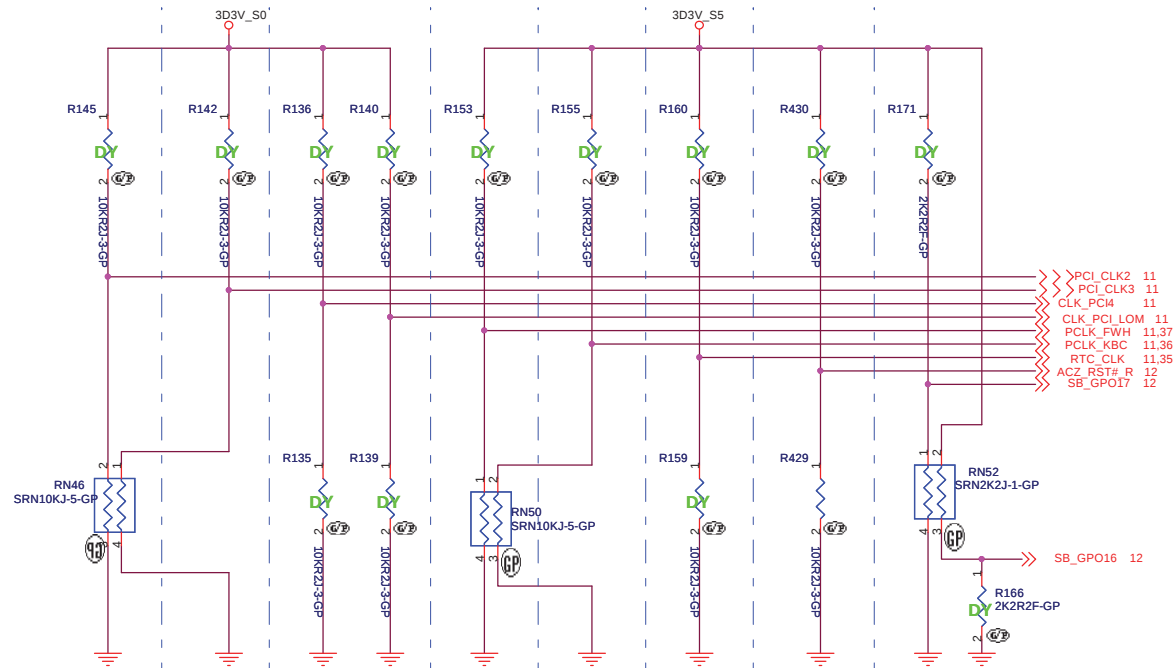


Dummy CKG select



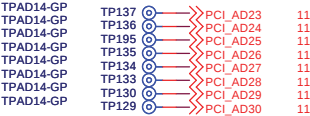
Layout connect to Cap then GND

REQUIRED STRAPS
REQUIRED SYSTEM STRAPS



NOTE: SB700 HAS INTERNAL 15K PULL UP RESISTOR FOR RTCCLK

DEBUG STRAPS



	PCI_CLK2	PCI_CLK3	CLK_PCI_LOM CLK_PCI4	PCLK_FWH	PCLK_KBC	RTCCLK	AZ_RST#	SB_GPO17 , SB_GPO16
PULL HIGH	WatchDOG (NB_PWRGD) ENABLED	USE DEBUG STRAPS	RESERVED	IMC ENABLED	CLKGEN ENABLED (Use Internal)	INTERNAL RTC DEFAULT	ENABLE PCI ROM BOOT	ROM TYPE: H, H = Reserved H, L = SPI ROM
PULL LOW	WatchDog (NB_PWRGD) DISABLED DEFAULT	IGNORE DEBUG STRAPS DEFAULT		IMC DISABLED DEFAULT	CLKGEN DISABLED (Use External) DEFAULT	EXT. RTC (PD on X1, apply 32KHz to RTC_CLK)	DISABLE PCI ROM BOOT DEFAULT	L, H = LPC ROM DEFAULT L, L = FWH ROM

	PCI_AD28	PCI_AD27	PCI_AD26	PCI_AD25	PCI_AD24	PCI_AD23	PCI_AD30 PCI_AD29
PULL HIGH	USE LONG RESET (DEFAULT)	USE PCI PLL (DEFAULT)	USE ACPI BCLK (DEFAULT)	USE IDE PLL (DEFAULT)	USE DEFAULT PCIE STRAPS (DEFAULT)	Reserved (DEFAULT)	Reserved
PULL LOW	USE SHORT RESET	BYPASS PCI PLL	BYPASS ACPI BCLK	BYPASS IDE PLL	USE EEPROM PCIE STRAPS	Reserved	

Note: SB700 has 15K internal PU FOR PCI_AD[30:23]

5,18 MEM_MA_ADD0 >> 102 A0
5,18 MEM_MA_ADD1 >> 101 A1
5,18 MEM_MA_ADD2 >> 100 A2
5,18 MEM_MA_ADD3 >> 99 A3
5,18 MEM_MA_ADD4 >> 98 A4
5,18 MEM_MA_ADD5 >> 97 A5
5,18 MEM_MA_ADD6 >> 96 A6
5,18 MEM_MA_ADD7 >> 95 A7
5,18 MEM_MA_ADD8 >> 94 A8
5,18 MEM_MA_ADD9 >> 93 A9
5,18 MEM_MA_ADD10 >> 92 A10/AP
5,18 MEM_MA_ADD11 >> 91 A11
5,18 MEM_MA_ADD12 >> 90 A12
5,18 MEM_MA_ADD13 >> 89 A13
5,18 MEM_MA_ADD14 >> 88 A14
5,18 MEM_MA_ADD15 >> 87 A15
5,18 MEM_MA_BANK0 >> 107 BA0
5,18 MEM_MA_BANK1 >> 106 BA1

5 MEM_MA_DATA0 >> 5 DQ0
5 MEM_MA_DATA1 >> 17 DQ1
5 MEM_MA_DATA2 >> 19 DQ2
5 MEM_MA_DATA3 >> 4 DQ3
5 MEM_MA_DATA4 >> 14 DQ4
5 MEM_MA_DATA5 >> 16 DQ5
5 MEM_MA_DATA6 >> 23 DQ6
5 MEM_MA_DATA7 >> 25 DQ7
5 MEM_MA_DATA8 >> 35 DQ8
5 MEM_MA_DATA9 >> 37 DQ9
5 MEM_MA_DATA10 >> 20 DQ10
5 MEM_MA_DATA11 >> 22 DQ11
5 MEM_MA_DATA12 >> 36 DQ12
5 MEM_MA_DATA13 >> 38 DQ13
5 MEM_MA_DATA14 >> 43 DQ14
5 MEM_MA_DATA15 >> 45 DQ15
5 MEM_MA_DATA16 >> 55 DQ16
5 MEM_MA_DATA17 >> 57 DQ17
5 MEM_MA_DATA18 >> 44 DQ18
5 MEM_MA_DATA19 >> 46 DQ19
5 MEM_MA_DATA20 >> 58 DQ20
5 MEM_MA_DATA21 >> 61 DQ21
5 MEM_MA_DATA22 >> 62 DQ22
5 MEM_MA_DATA23 >> 73 DQ23
5 MEM_MA_DATA24 >> 75 DQ24
5 MEM_MA_DATA25 >> 63 DQ25
5 MEM_MA_DATA26 >> 74 DQ26
5 MEM_MA_DATA27 >> 76 DQ27
5 MEM_MA_DATA28 >> 64 DQ28
5 MEM_MA_DATA29 >> 74 DQ29
5 MEM_MA_DATA30 >> 123 DQ30
5 MEM_MA_DATA31 >> 125 DQ31
5 MEM_MA_DATA32 >> 135 DQ32
5 MEM_MA_DATA33 >> 137 DQ33
5 MEM_MA_DATA34 >> 124 DQ34
5 MEM_MA_DATA35 >> 126 DQ35
5 MEM_MA_DATA36 >> 134 DQ36
5 MEM_MA_DATA37 >> 136 DQ37
5 MEM_MA_DATA38 >> 138 DQ38
5 MEM_MA_DATA39 >> 141 DQ39
5 MEM_MA_DATA40 >> 143 DQ40
5 MEM_MA_DATA41 >> 151 DQ41
5 MEM_MA_DATA42 >> 153 DQ42
5 MEM_MA_DATA43 >> 140 DQ43
5 MEM_MA_DATA44 >> 142 DQ44
5 MEM_MA_DATA45 >> 154 DQ45
5 MEM_MA_DATA46 >> 157 DQ46
5 MEM_MA_DATA47 >> 159 DQ47
5 MEM_MA_DATA48 >> 173 DQ48
5 MEM_MA_DATA49 >> 175 DQ49
5 MEM_MA_DATA50 >> 158 DQ50
5 MEM_MA_DATA51 >> 160 DQ51
5 MEM_MA_DATA52 >> 174 DQ52
5 MEM_MA_DATA53 >> 176 DQ53
5 MEM_MA_DATA54 >> 178 DQ54
5 MEM_MA_DATA55 >> 181 DQ55
5 MEM_MA_DATA56 >> 183 DQ56
5 MEM_MA_DATA57 >> 185 DQ57
5 MEM_MA_DATA58 >> 187 DQ58
5 MEM_MA_DATA59 >> 189 DQ59
5 MEM_MA_DATA60 >> 191 DQ60
5 MEM_MA_DATA61 >> 193 DQ61
5 MEM_MA_DATA62 >> 195 DQ62
5 MEM_MA_DATA63 >> 197 DQ63

5 MEM_MA_DQS0_N >> 11 DQS0#
5 MEM_MA_DQS1_N >> 29 DQS1#
5 MEM_MA_DQS2_N >> 49 DQS2#
5 MEM_MA_DQS3_N >> 68 DQS3#
5 MEM_MA_DQS4_N >> 122 DQS4#
5 MEM_MA_DQS5_N >> 146 DQS5#
5 MEM_MA_DQS6_N >> 167 DQS6#
5 MEM_MA_DQS7_N >> 186 DQS7#

5 MEM_MA_DQS0_P >> 13 DQS0#
5 MEM_MA_DQS1_P >> 31 DQS1#
5 MEM_MA_DQS2_P >> 51 DQS2#
5 MEM_MA_DQS3_P >> 70 DQS3#
5 MEM_MA_DQS4_P >> 131 DQS4#
5 MEM_MA_DQS5_P >> 148 DQS5#
5 MEM_MA_DQS6_P >> 169 DQS6#
5 MEM_MA_DQS7_P >> 188 DQS7#

5,18 MEM_MA0_ODT0 >> 114 OTD0
5,18 MEM_MA0_ODT1 >> 119 OTD1

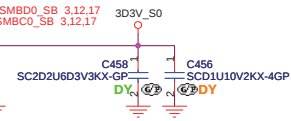


Place C2.2uF and 0.1uF <
500mils from DDR connector

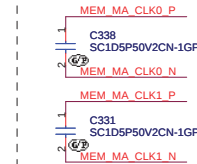
NORMAL TYPE

ADIMM2
RAS# 108
WE# 109
CAS# 113
CS0# 110
CS1# 115
CKE0 79
CKE1 80
CK0 30
CK0# 32
CK1 164
CK1# 166
DM0 10
DM1 26
DM2 52
DM3 67
DM4 130
DM5 147
DM6 170
DM7 185
SDA 195
SCL 197
VDDSPD 199
SA0 198
SA1 200
NC#50 50
NC#69 69
NC#83 83
NC#120 120
NC#163TEST 163
VDD 81
VDD 82
VDD 87
VDD 88
VDD 95
VDD 96
VDD 103
VDD 104
VDD 111
VDD 112
VDD 117
VDD 118
VSS 3
VSS 8
VSS 9
VSS 12
VSS 15
VSS 18
VSS 21
VSS 27
VSS 28
VSS 33
VSS 34
VSS 39
VSS 40
VSS 41
VSS 42
VSS 47
VSS 48
VSS 53
VSS 54
VSS 59
VSS 60
VSS 65
VSS 66
VSS 71
VSS 72
VSS 77
VSS 78
VSS 121
VSS 122
VSS 127
VSS 128
VSS 132
VSS 133
VSS 138
VSS 139
VSS 144
VSS 145
VSS 149
VSS 150
VSS 155
VSS 156
VSS 161
VSS 162
VSS 165
VSS 168
VSS 171
VSS 172
VSS 177
VSS 178
VSS 183
VSS 184
VSS 187
VSS 190
VSS 193
VSS 196
VSS 201
GND 201
MH2 GP

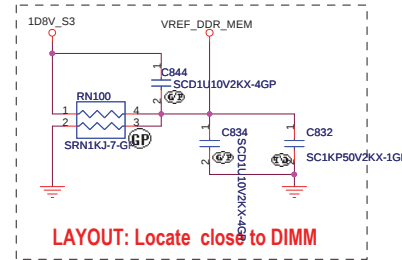
MEM_MA_RAS# 5,18
MEM_MA_WE# 5,18
MEM_MA_CAS# 5,18
MEM_MA_CS#0 5,18
MEM_MA_CS#1 5,18
MEM_MA_CKE0 5,18
MEM_MA_CKE1 5,18
MEM_MA_CLK0_P 5
MEM_MA_CLK0_N 5
MEM_MA_CLK1_P 5
MEM_MA_CLK1_N 5
MEM_MA_DM0 5
MEM_MA_DM1 5
MEM_MA_DM2 5
MEM_MA_DM3 5
MEM_MA_DM4 5
MEM_MA_DM5 5
MEM_MA_DM6 5
MEM_MA_DM7 5



PLACE CLOSE TO PROCESSOR
WITHIN 1.5 INCH



DDR_VREF



<Core Design>

緯創資通 Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title: DDR SO-DIMM SKT 1
Size: Custom Document Number: JV50-TR Rev: SB
Date: Tuesday, June 16, 2009 Sheet: 16 of 61

LOW 5.2 mm

5,18 MEM_MB_ADD0 >>> 102 A0
5,18 MEM_MB_ADD1 >>> 101 A1
5,18 MEM_MB_ADD2 >>> 100 A2
5,18 MEM_MB_ADD3 >>> 99 A3
5,18 MEM_MB_ADD4 >>> 98 A4
5,18 MEM_MB_ADD5 >>> 97 A5
5,18 MEM_MB_ADD6 >>> 96 A6
5,18 MEM_MB_ADD7 >>> 95 A7
5,18 MEM_MB_ADD8 >>> 94 A8
5,18 MEM_MB_ADD9 >>> 93 A9
5,18 MEM_MB_ADD10 >>> 92 A10/AP
5,18 MEM_MB_ADD11 >>> 91 A11
5,18 MEM_MB_ADD12 >>> 90 A12
5,18 MEM_MB_ADD13 >>> 89 A13
5,18 MEM_MB_ADD14 >>> 88 A14
5,18 MEM_MB_ADD15 >>> 87 A15

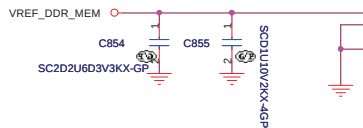
5,18 MEM_MB_BANK2 >>> 107 BA0
5,18 MEM_MB_BANK0 >>> 106 BA1
5,18 MEM_MB_BANK1 >>> 105 BA2

5 MEM_MB_DATA0 >>> 5 DQ0
5 MEM_MB_DATA1 >>> 7 DQ1
5 MEM_MB_DATA2 >>> 17 DQ2
5 MEM_MB_DATA3 >>> 19 DQ3
5 MEM_MB_DATA4 >>> 4 DQ4
5 MEM_MB_DATA5 >>> 6 DQ5
5 MEM_MB_DATA6 >>> 14 DQ6
5 MEM_MB_DATA7 >>> 16 DQ7
5 MEM_MB_DATA8 >>> 23 DQ8
5 MEM_MB_DATA9 >>> 25 DQ9
5 MEM_MB_DATA10 >>> 35 DQ10
5 MEM_MB_DATA11 >>> 37 DQ11
5 MEM_MB_DATA12 >>> 20 DQ12
5 MEM_MB_DATA13 >>> 22 DQ13
5 MEM_MB_DATA14 >>> 36 DQ14
5 MEM_MB_DATA15 >>> 38 DQ15
5 MEM_MB_DATA16 >>> 43 DQ16
5 MEM_MB_DATA17 >>> 45 DQ17
5 MEM_MB_DATA18 >>> 55 DQ18
5 MEM_MB_DATA19 >>> 57 DQ19
5 MEM_MB_DATA20 >>> 44 DQ20
5 MEM_MB_DATA21 >>> 46 DQ21
5 MEM_MB_DATA22 >>> 58 DQ22
5 MEM_MB_DATA23 >>> 61 DQ23
5 MEM_MB_DATA24 >>> 59 DQ24
5 MEM_MB_DATA25 >>> 63 DQ25
5 MEM_MB_DATA26 >>> 73 DQ26
5 MEM_MB_DATA27 >>> 75 DQ27
5 MEM_MB_DATA28 >>> 62 DQ28
5 MEM_MB_DATA29 >>> 64 DQ29
5 MEM_MB_DATA30 >>> 76 DQ30
5 MEM_MB_DATA31 >>> 123 DQ31
5 MEM_MB_DATA32 >>> 125 DQ32
5 MEM_MB_DATA33 >>> 126 DQ33
5 MEM_MB_DATA34 >>> 137 DQ34
5 MEM_MB_DATA35 >>> 124 DQ35
5 MEM_MB_DATA36 >>> 126 DQ36
5 MEM_MB_DATA37 >>> 134 DQ37
5 MEM_MB_DATA38 >>> 136 DQ38
5 MEM_MB_DATA39 >>> 141 DQ39
5 MEM_MB_DATA40 >>> 143 DQ40
5 MEM_MB_DATA41 >>> 151 DQ41
5 MEM_MB_DATA42 >>> 153 DQ42
5 MEM_MB_DATA43 >>> 140 DQ43
5 MEM_MB_DATA44 >>> 142 DQ44
5 MEM_MB_DATA45 >>> 152 DQ45
5 MEM_MB_DATA46 >>> 154 DQ46
5 MEM_MB_DATA47 >>> 157 DQ47
5 MEM_MB_DATA48 >>> 159 DQ48
5 MEM_MB_DATA49 >>> 173 DQ49
5 MEM_MB_DATA50 >>> 175 DQ50
5 MEM_MB_DATA51 >>> 158 DQ51
5 MEM_MB_DATA52 >>> 160 DQ52
5 MEM_MB_DATA53 >>> 174 DQ53
5 MEM_MB_DATA54 >>> 176 DQ54
5 MEM_MB_DATA55 >>> 179 DQ55
5 MEM_MB_DATA56 >>> 181 DQ56
5 MEM_MB_DATA57 >>> 189 DQ57
5 MEM_MB_DATA58 >>> 191 DQ58
5 MEM_MB_DATA59 >>> 180 DQ59
5 MEM_MB_DATA60 >>> 182 DQ60
5 MEM_MB_DATA61 >>> 192 DQ61
5 MEM_MB_DATA62 >>> 186 DQ62
5 MEM_MB_DATA63 >>> 194 DQ63

5 MEM_MB_DQS0_N >>> 110 DQS0#
5 MEM_MB_DQS1_N >>> 29 DQS1#
5 MEM_MB_DQS2_N >>> 49 DQS2#
5 MEM_MB_DQS3_N >>> 68 DQS3#
5 MEM_MB_DQS4_N >>> 129 DQS4#
5 MEM_MB_DQS5_N >>> 146 DQS5#
5 MEM_MB_DQS6_N >>> 167 DQS6#
5 MEM_MB_DQS7_N >>> 186 DQS7#

5 MEM_MB_DQS0_P >>> 13 DQS0
5 MEM_MB_DQS1_P >>> 31 DQS1
5 MEM_MB_DQS2_P >>> 51 DQS2
5 MEM_MB_DQS3_P >>> 70 DQS3
5 MEM_MB_DQS4_P >>> 131 DQS4
5 MEM_MB_DQS5_P >>> 148 DQS5
5 MEM_MB_DQS6_P >>> 169 DQS6
5 MEM_MB_DQS7_P >>> 188 DQS7

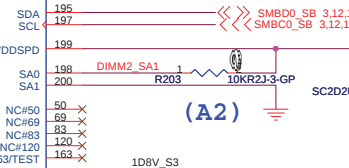
5,18 MEM_MB_ODT0 >>> 114 ODT0
5,18 MEM_MB_ODT1 >>> 119 ODT1



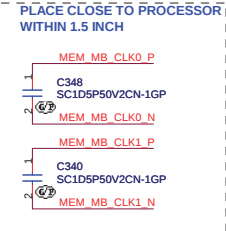
Place C2.2uF and 0.1uF < 500mils from DDR connector

NORMAL TYPE

RAS# 108 A0
WE# 109 A1
CAS# 113 A2
CS0# 110 A3
CS1# 115 A4
CKE0 79 A5
CKE1 80 A6
CK0 30 A7
CK0# 32 A8
CK1 164 A9
CK1# 166 A10/AP
DM0 10 A11
DM1 26 A12
DM2 52 A13
DM3 130 A14
DM4 147 A15
DM5 170 A16/BA2
DM6 185 BA0
DM7 185 BA1



VDD 81
VDD 82
VDD 87
VDD 88
VDD 95
VDD 96
VDD 103
VDD 104
VDD 111
VDD 112
VDD 127
VDD 117
VDD 118
VSS 3
VSS 8
VSS 9
VSS 12
VSS 15
VSS 18
VSS 21
VSS 24
VSS 27
VSS 28
VSS 28
VSS 33
VSS 34
VSS 39
VSS 40
VSS 41
VSS 42
VSS 47
VSS 48
VSS 49
VSS 53
VSS 54
VSS 59
VSS 60
VSS 65
VSS 66
VSS 71
VSS 72
VSS 77
VSS 78
VSS 121
VSS 122
VSS 127
VSS 128
VSS 132
VSS 133
VSS 138
VSS 139
VSS 144
VSS 145
VSS 149
VSS 150
VSS 155
VSS 156
VSS 161
VSS 162
VSS 165
VSS 168
VSS 171
VSS 172
VSS 173
VSS 177
VSS 178
VSS 183
VSS 184
VSS 187
VSS 190
VSS 193
VSS 196
GND 201
GND 202
MH2 GP



DDR2-200P-22-GP-U3
62.10017.A61

2ND = 62.10017.A51 3RD = 62.10017.G71

HI 9.2mm

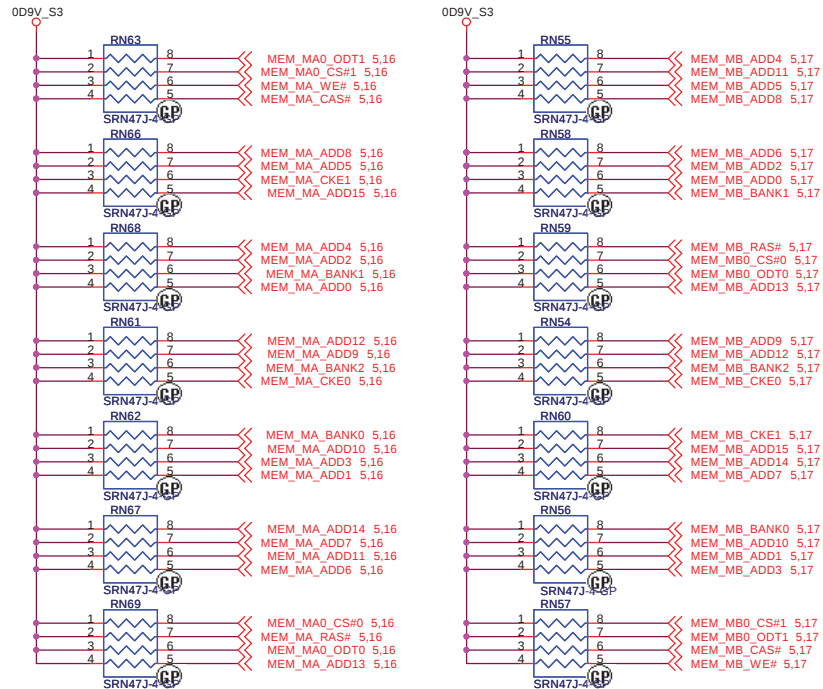
1ST change to 62.10017.E21

<Core Design>

緯創資通 Wistron Corporation	
2F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title	
DDR SO-DIMM SKT 2	
Size	Document Number
Custom	JV50-TR
Date: Tuesday, June 16, 2009	Sheet 17 of 61
Rev	SB

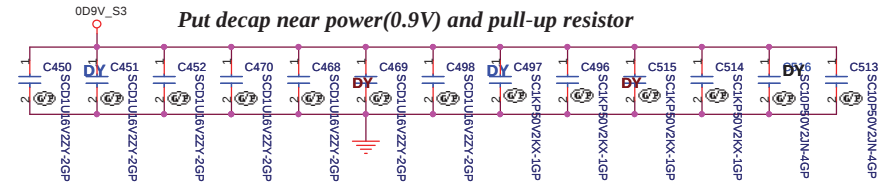
PARALLEL TERMINATION

Put decap near power(0.9V) and pull-up resistor

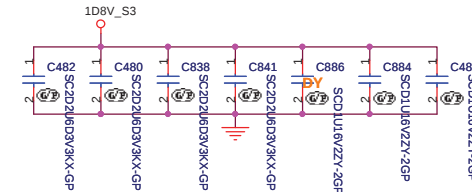


Do not share the Term resistor between the DDR address and Control Signals.

Decoupling Capacitor

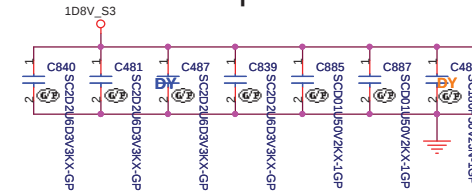


Place these Caps near DM1



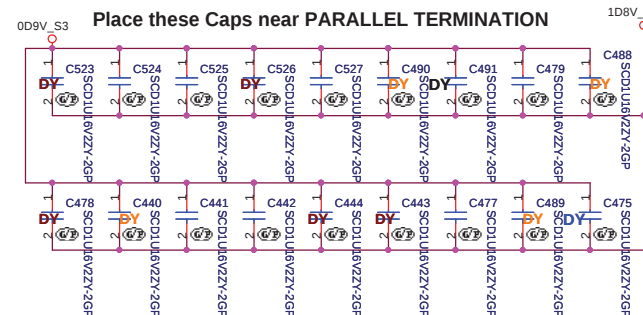
Layout Note:
Place one cap close to every 2 pullup resistors terminated to 0D9V_S3

Place these Caps near DM2



Layout Note:
Place one cap close to every 2 pullup resistors terminated to 0D9V_S3

Place these Caps near PARALLEL TERMINATION

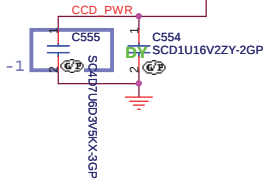
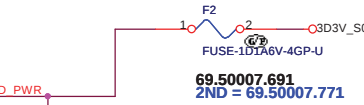
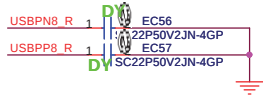
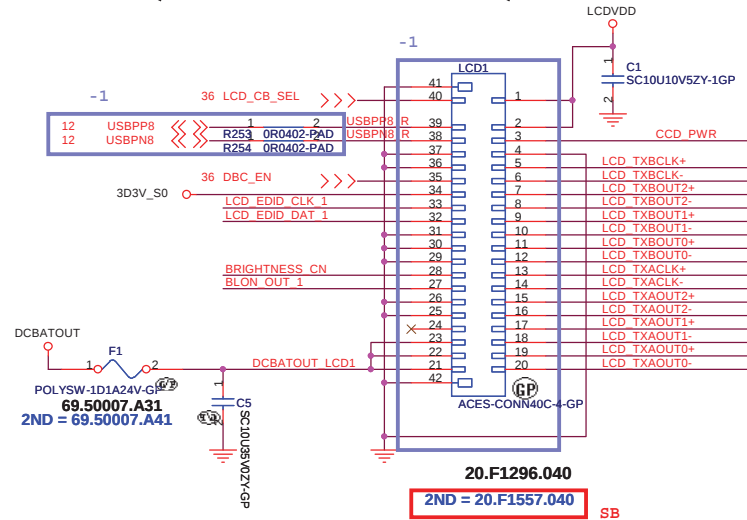


<Core Design>

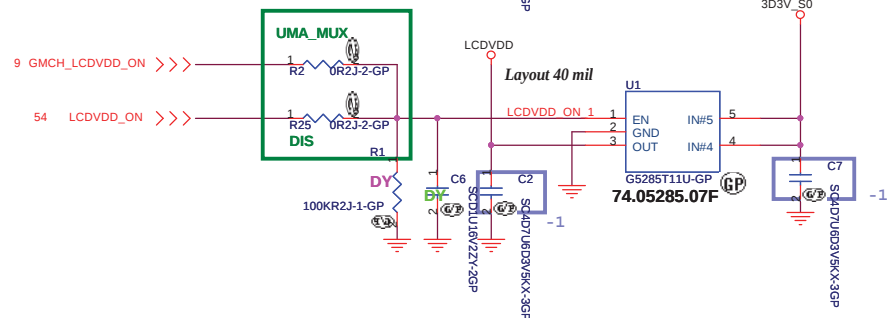
緯創資通 Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title		
DDR DAMPING & TERMINATION		
Size	Document Number	Rev
A3	JV50-TR	SB
Date:	Tuesday, June 16, 2009	Sheet 18 of 61

LCD/INVERTER/CCD CONN



for TR



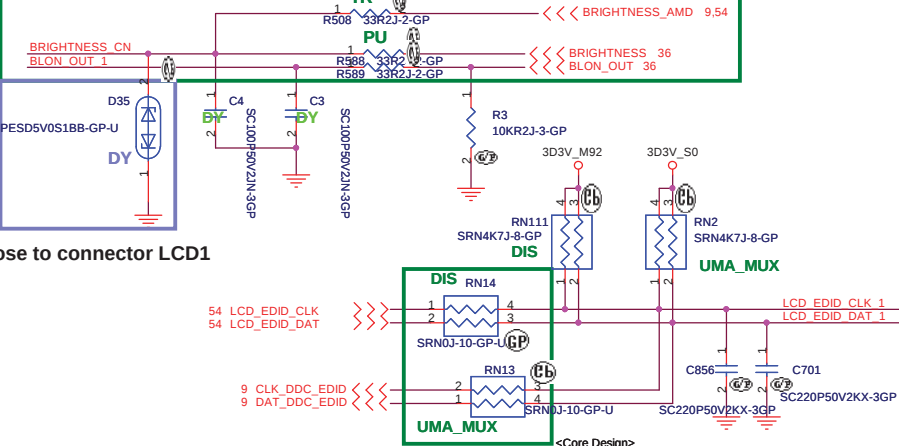
for TR



Inverter Pin	
Pin	Symbol
1	Vin
2	Vin
3	Brightness
4	BLON
5	GND
6	GND

CCD Pin	
Pin	Symbol
1	CCD_PWR
2	USB-
3	USB+
4	GND
5	GND

Close to connector LCD1



for TR

緯創資通 Wistron Corporation

21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

Title

LCD CONN

Size A3

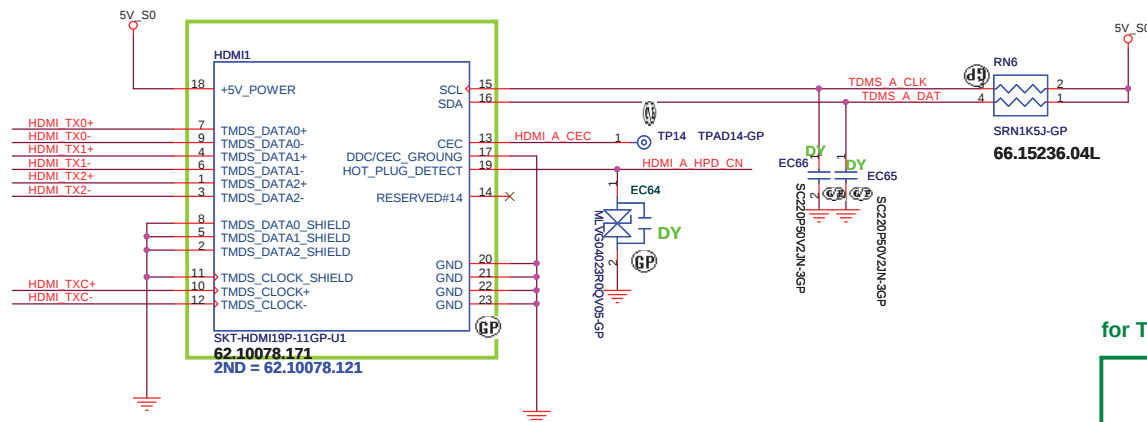
Document Number

JV50-TR

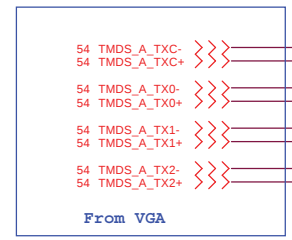
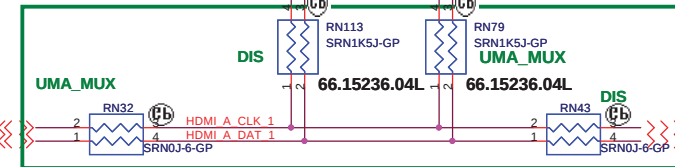
Date: Tuesday, June 16, 2009

Sheet 19 of 61

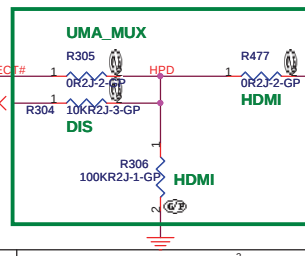
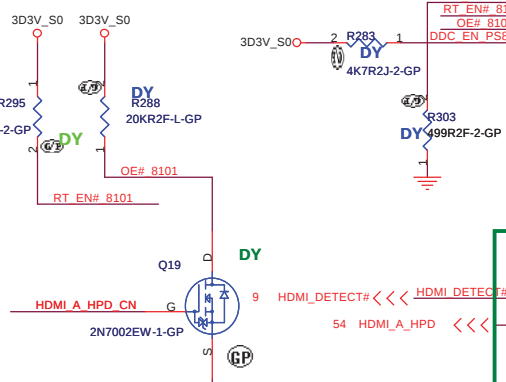
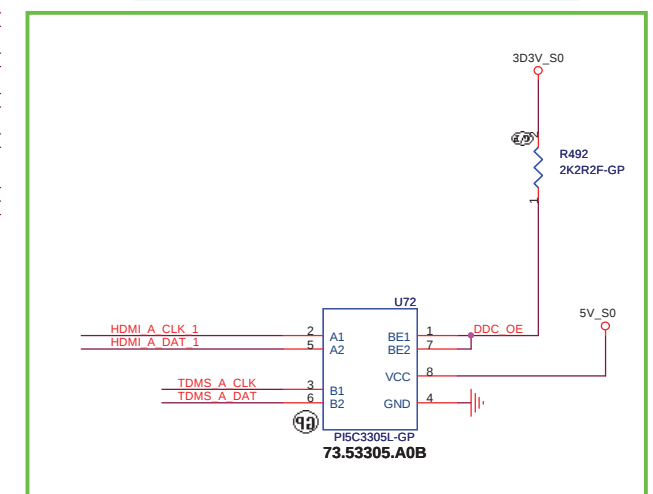
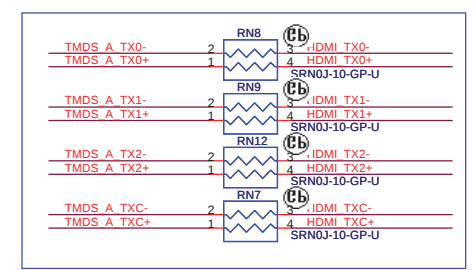
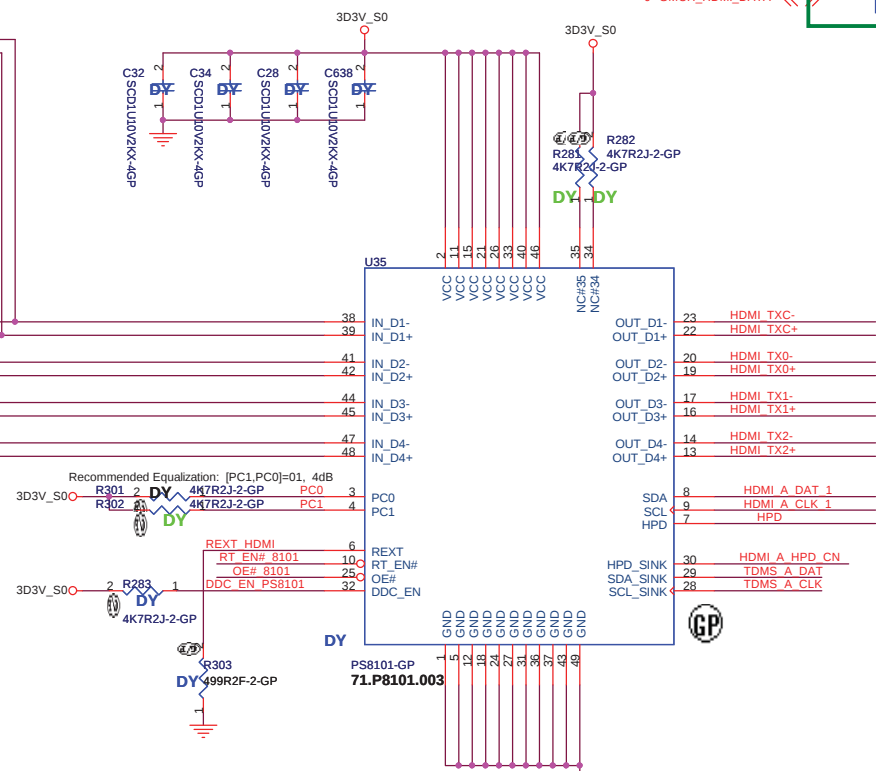
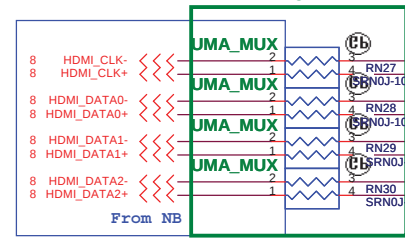
Rev SB



for TR



for TR



for TR

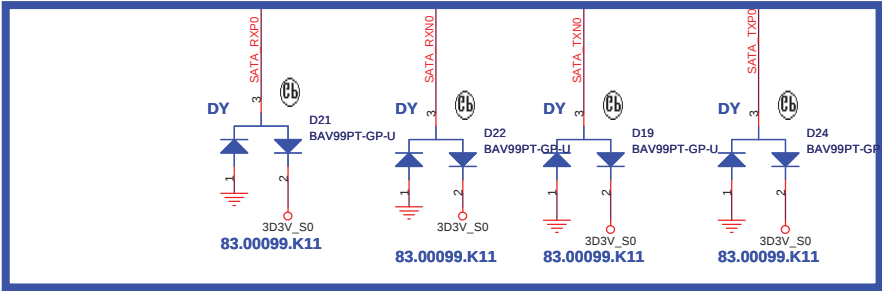
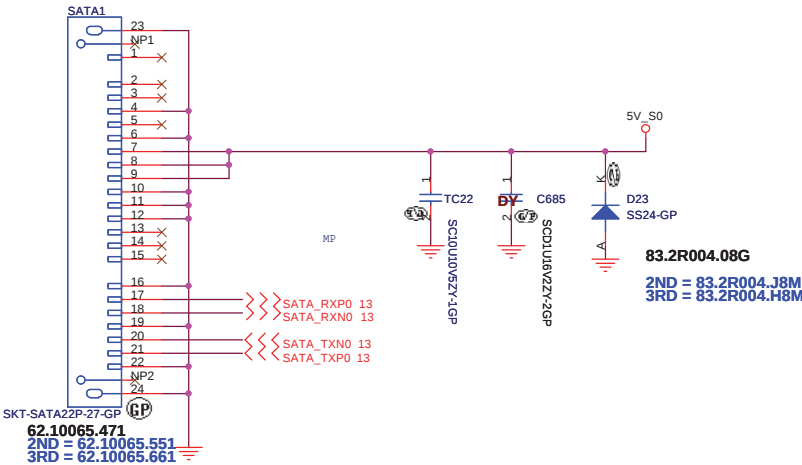
R477 : PU & TR-DIS-->0R
PU & TR-UMA & MUXLESS-->5.1K

R306 : PU & TR-DIS-->100K
PU & TR-UMA & MUXLESS-->10K

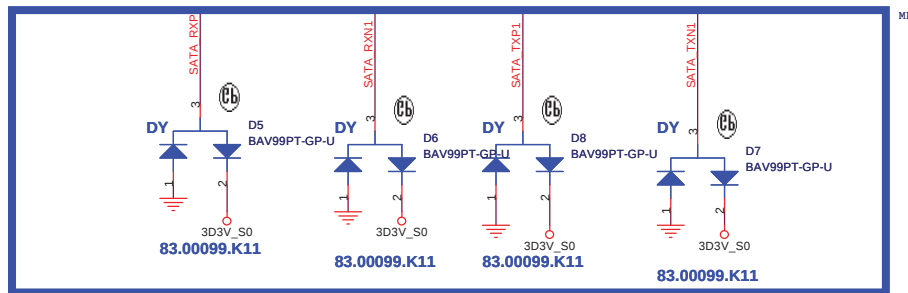
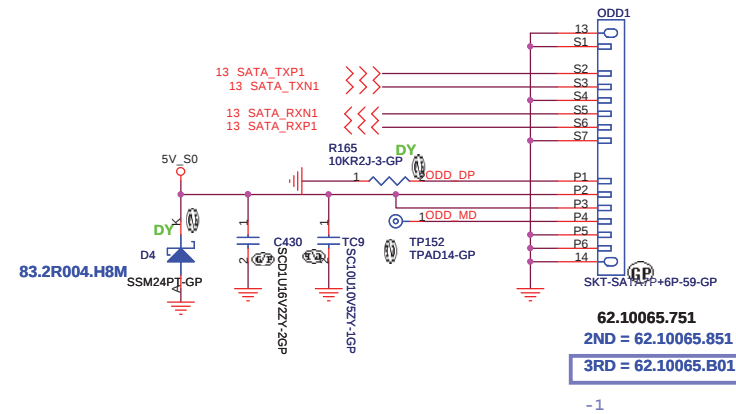
<Core Design>

緯創資通 Wistron Corporation		21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title HDMI Connector			
Size	Document Number	Rev	
JV50-TR		SB	
Date: Tuesday, June 16, 2009	Sheet 21	of 61	

SATA Connector

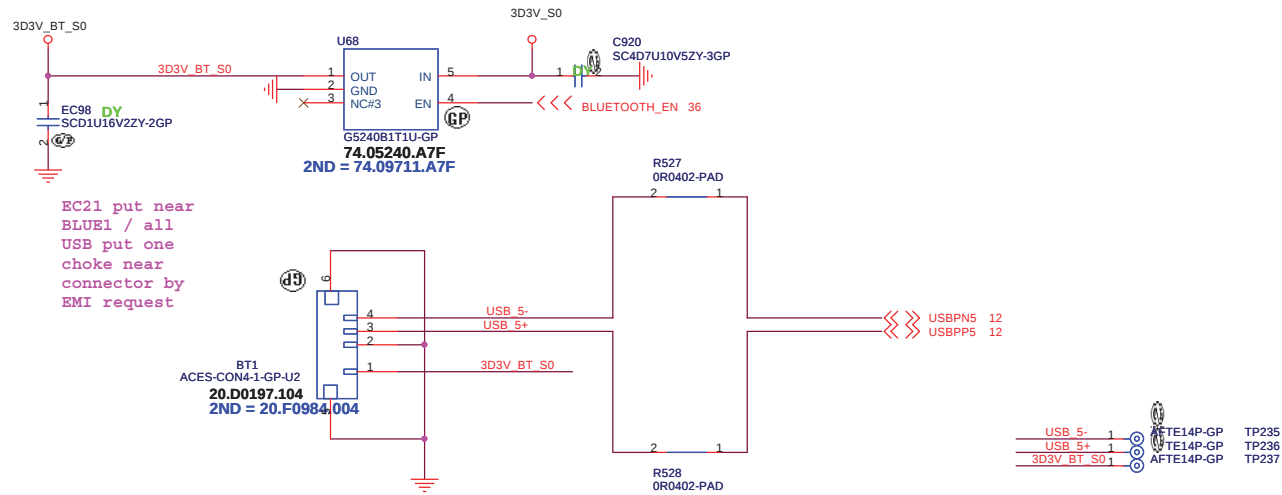


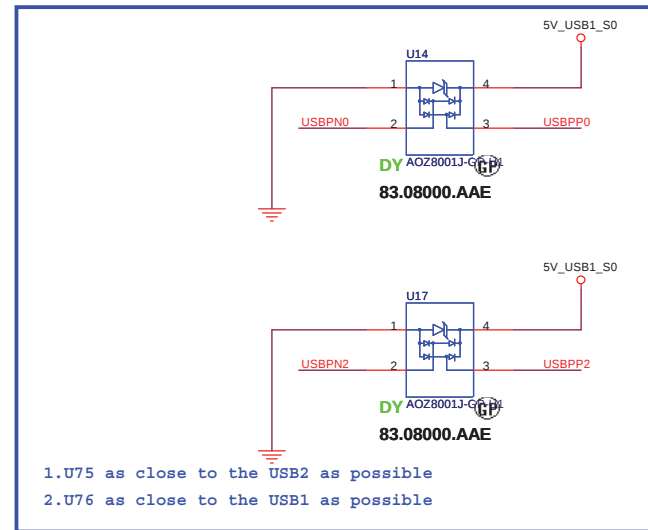
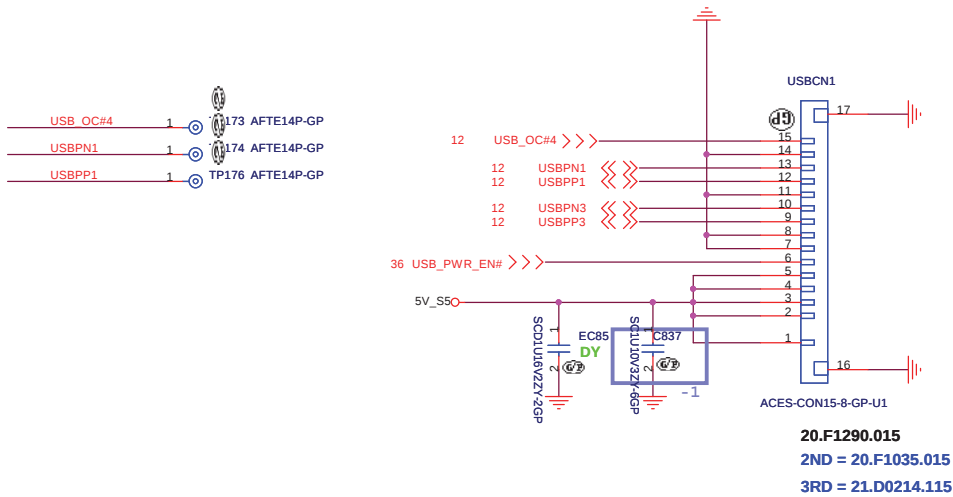
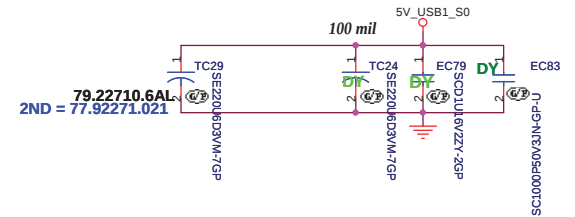
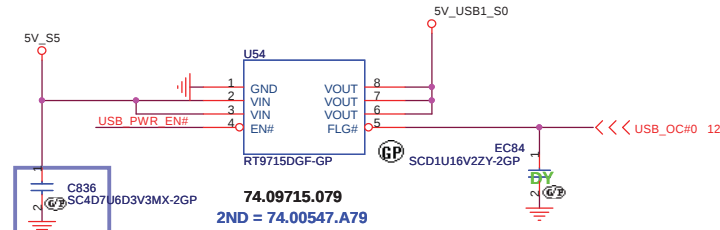
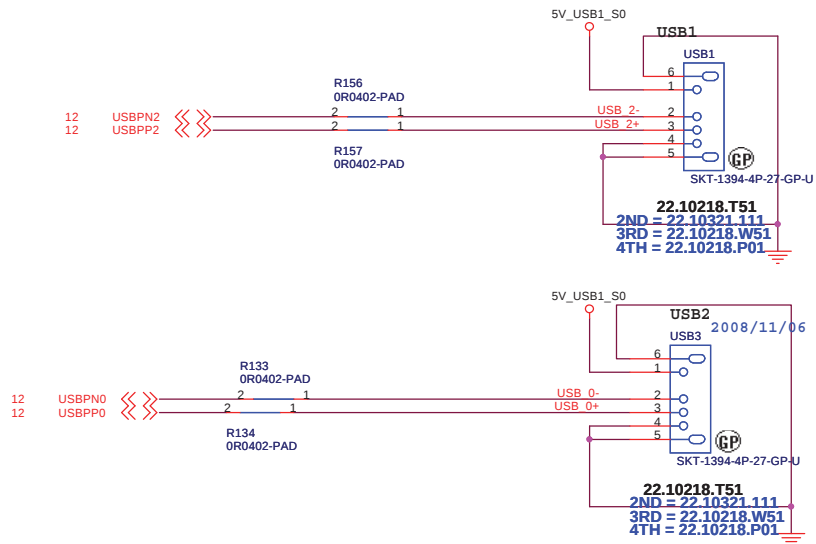
SATA ODD Connector



BLUETOOTH MODULE

1.5A / High Active Voltage 2V

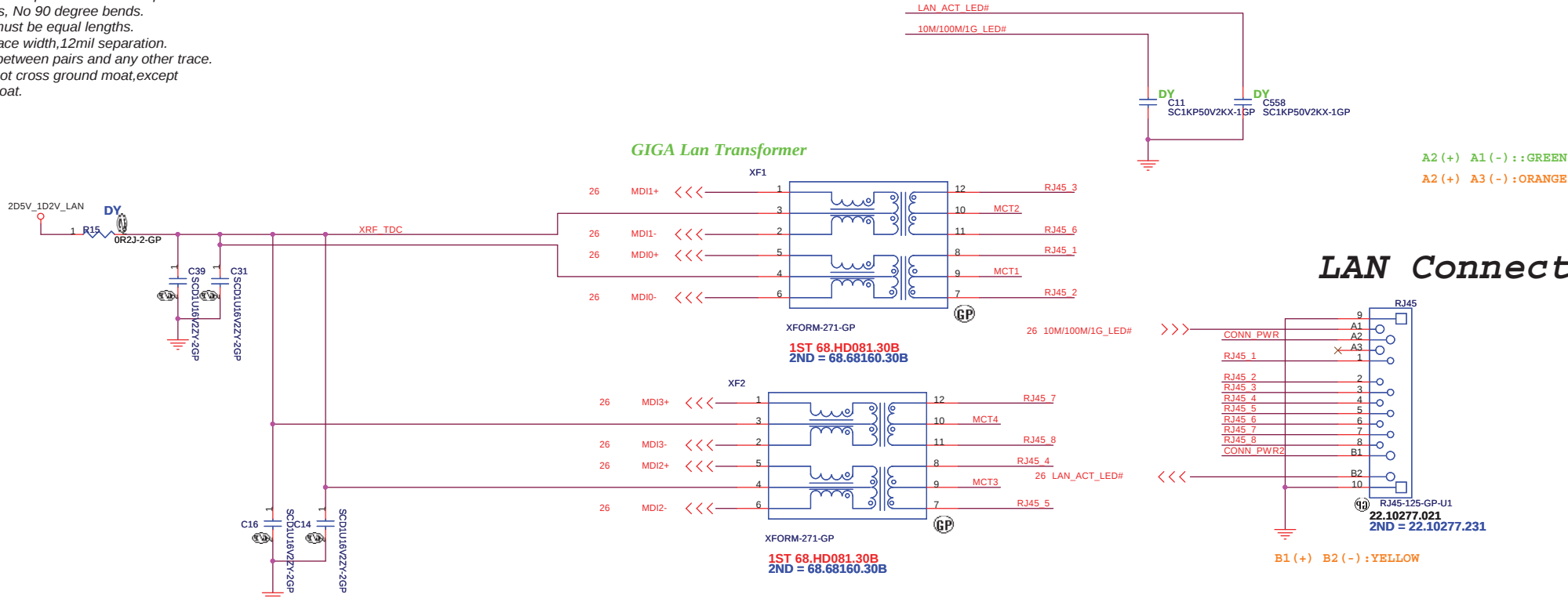






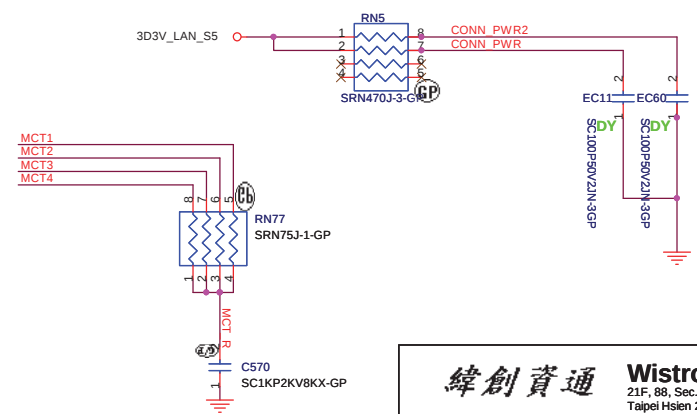
LAN Connector

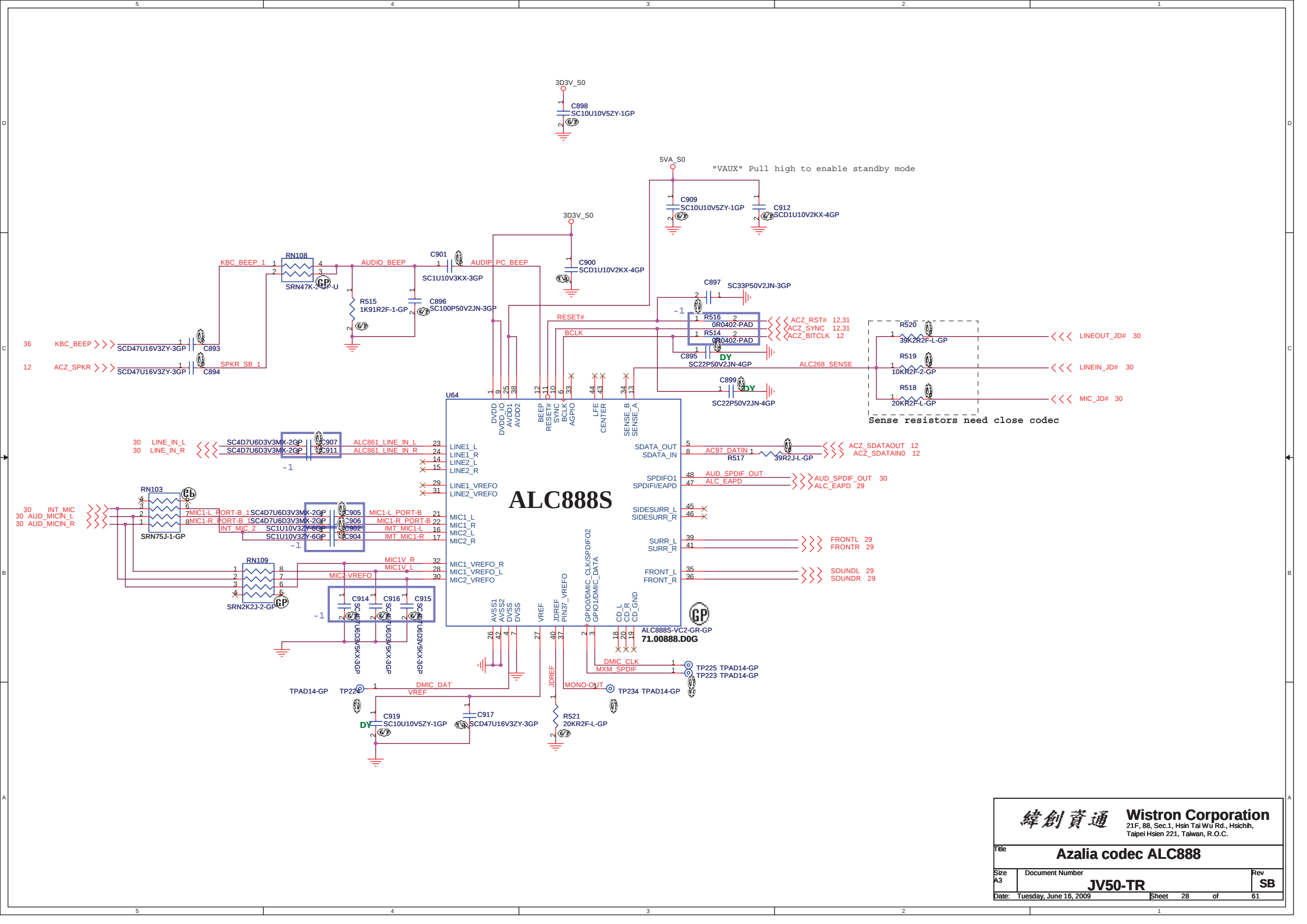
- 1.route on bottom as differential pairs.
- 2.Tx+/Tx- are pairs. Rx+/Rx- are pairs.
- 3.No vias, No 90 degree bends.
- 4.pairs must be equal lengths.
- 5.6mil trace width,12mil separation.
- 6.36mil between pairs and any other trace.
- 7.Must not cross ground moat,except RJ-45 moat.

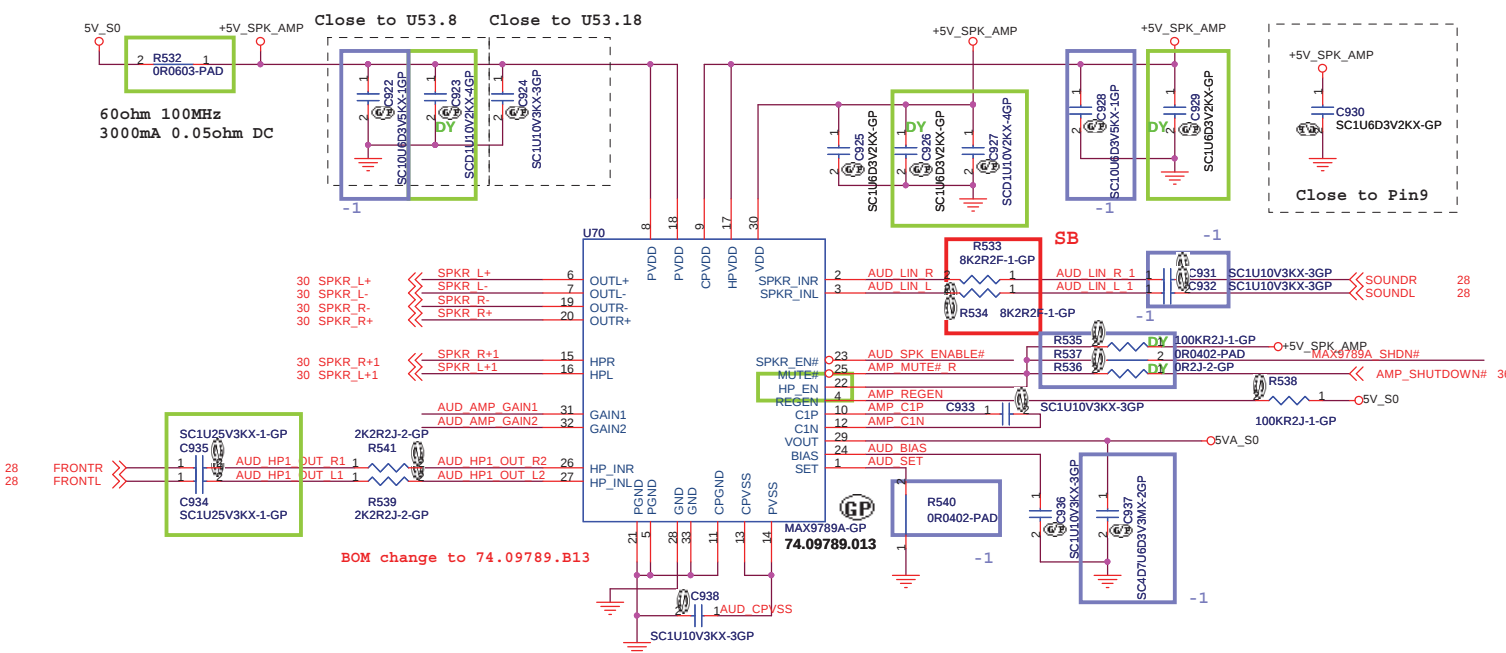


LAN Connector

DOC_TIP,DOC_RING,TIP,RING:
W/S : 10/100 @ Surface layers
10/20 @ Inner layers

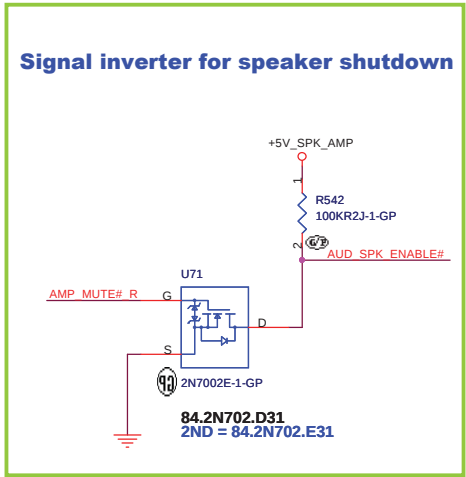
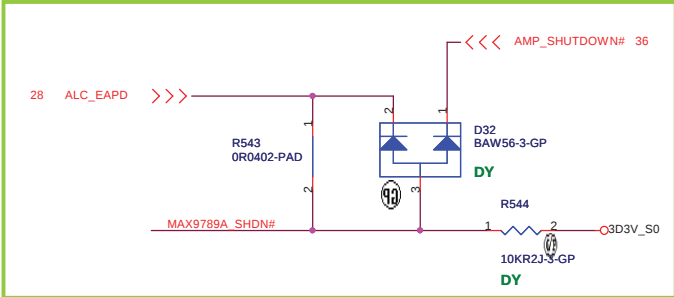




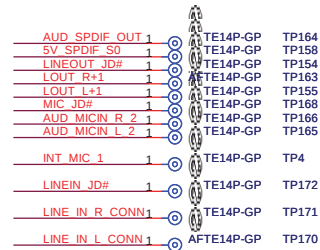
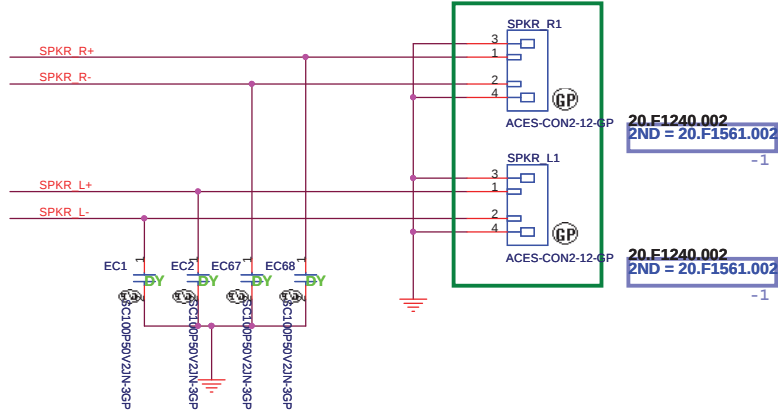
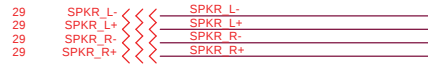


GAIN SETTING

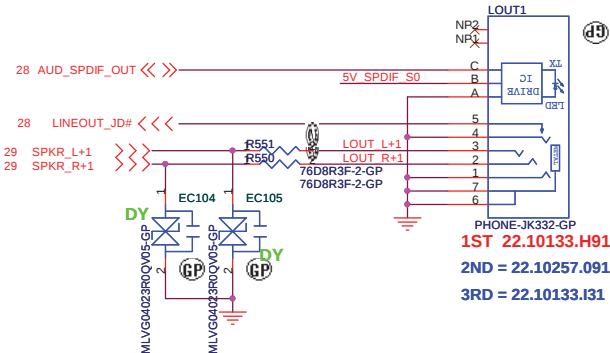
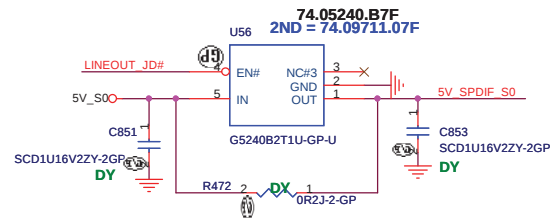
GAIN1	GAIN2	GAIN
0	0	6dB
0	1	10dB
1	0	15.6dB
1	1	21.6dB



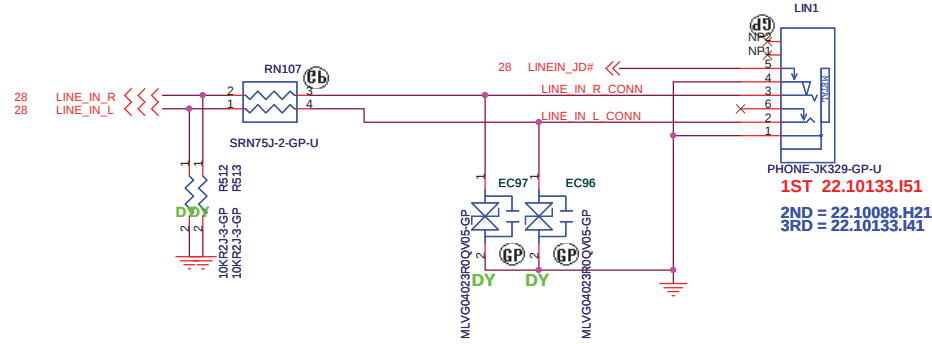
Internal Speaker



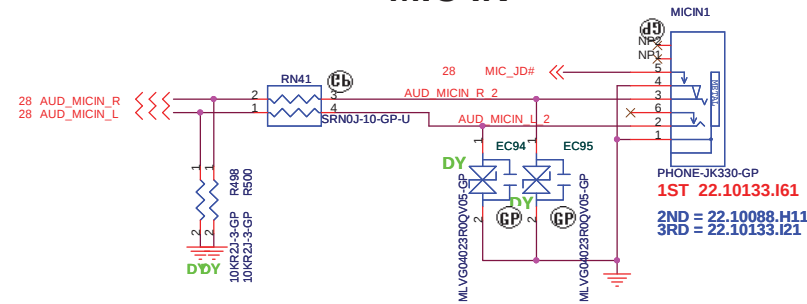
LINE OUT



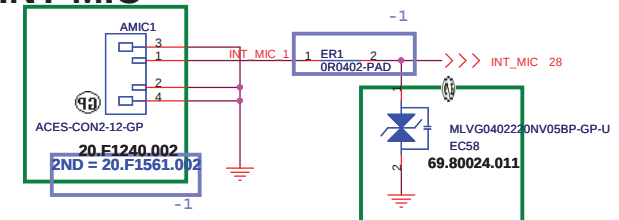
LINE IN



MIC IN



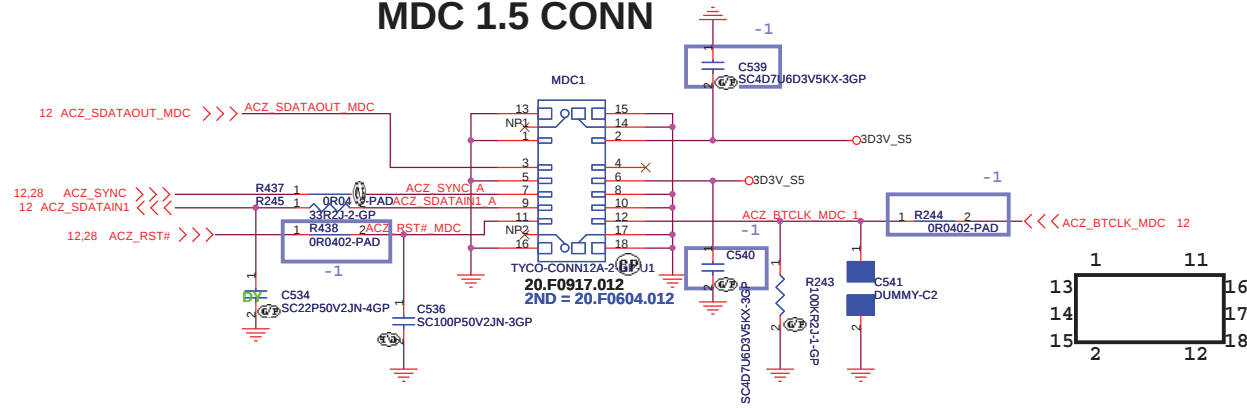
INT MIC

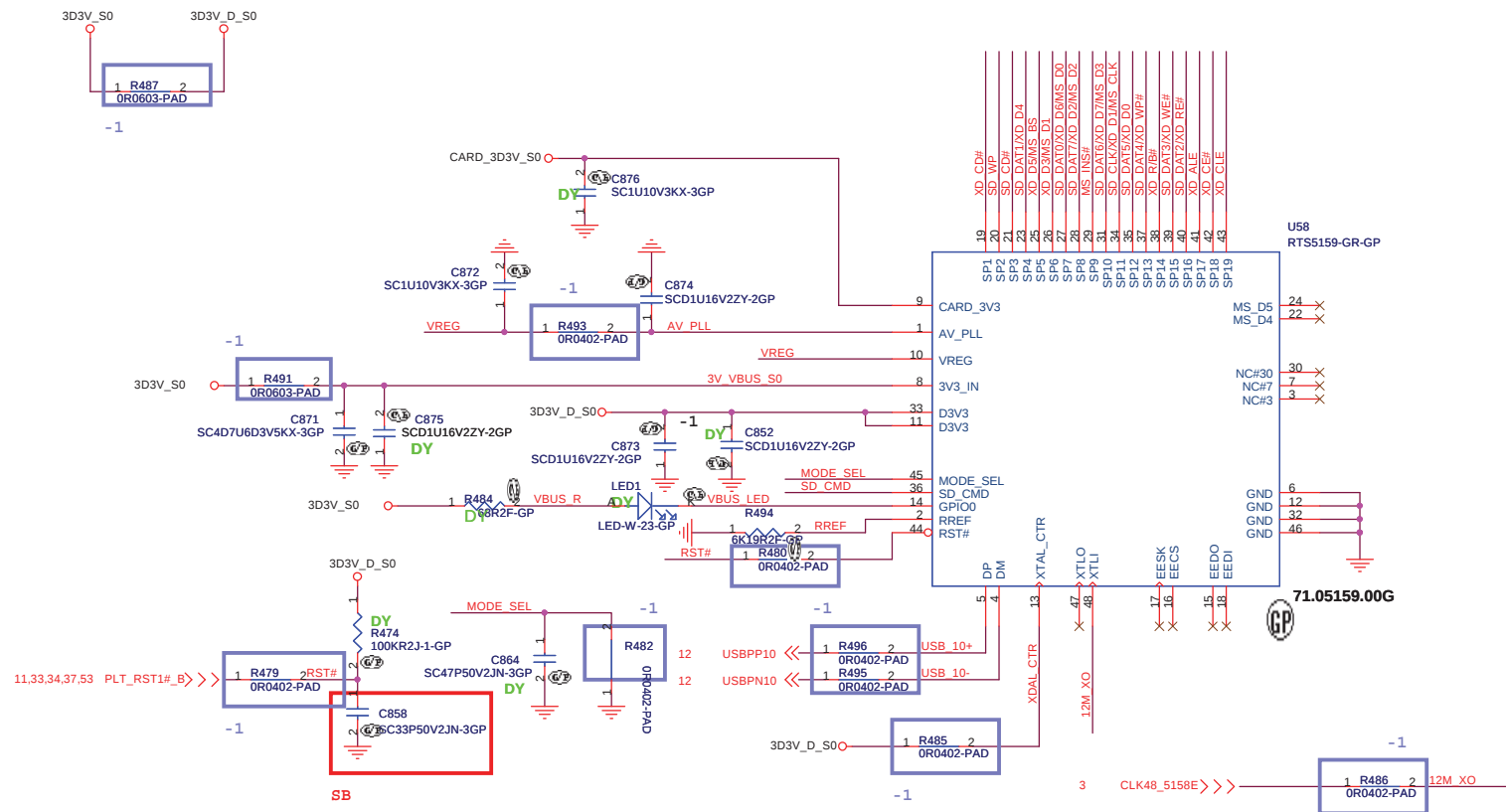


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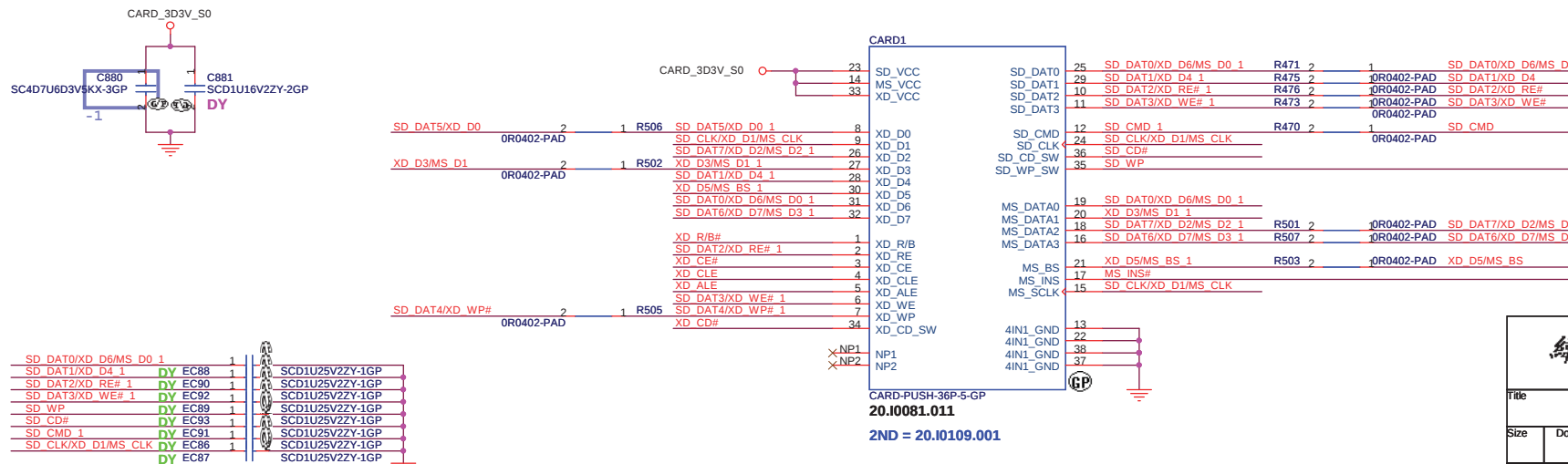
AUDIO JACK			Rev
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MDC 1.5 CONN





5 IN1 CARD-READER (SD/MMC/MS/MS PRO/XD)



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File

Size

Date: Tuesday, June 16, 2009

CARDREADER- RTS5159

Document Number

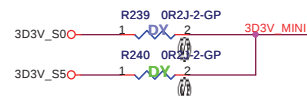
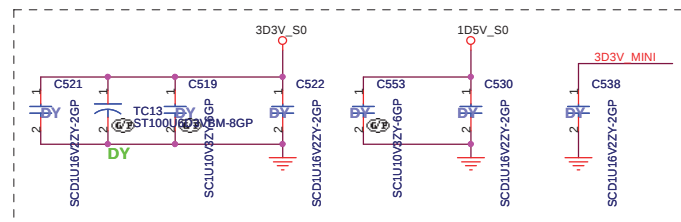
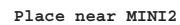
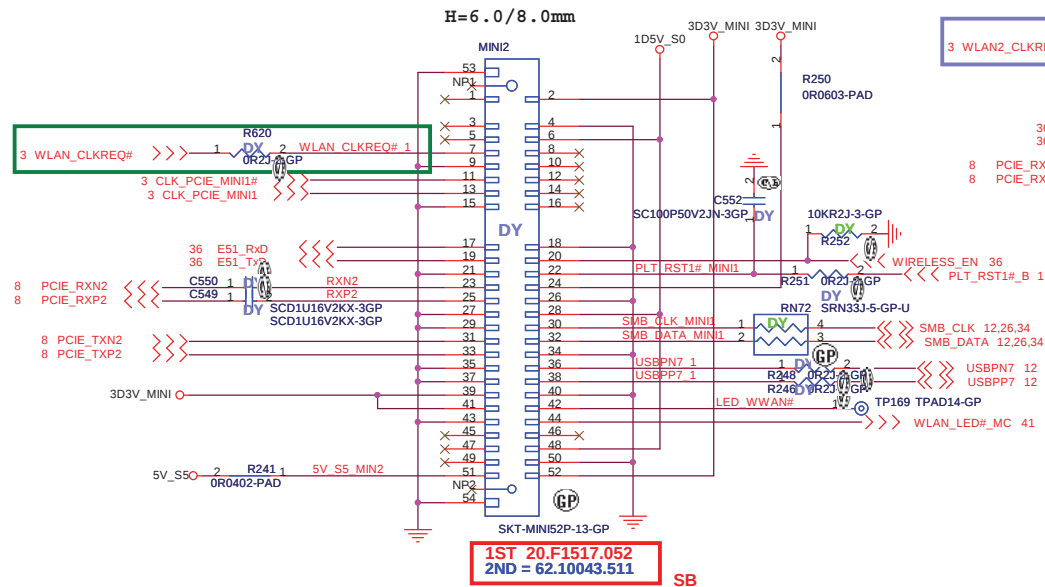
JV50-TR

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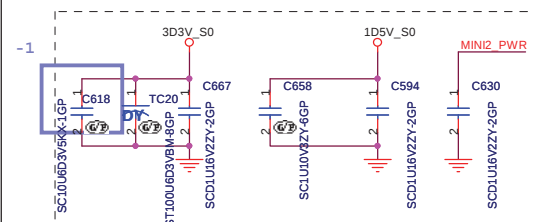
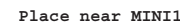
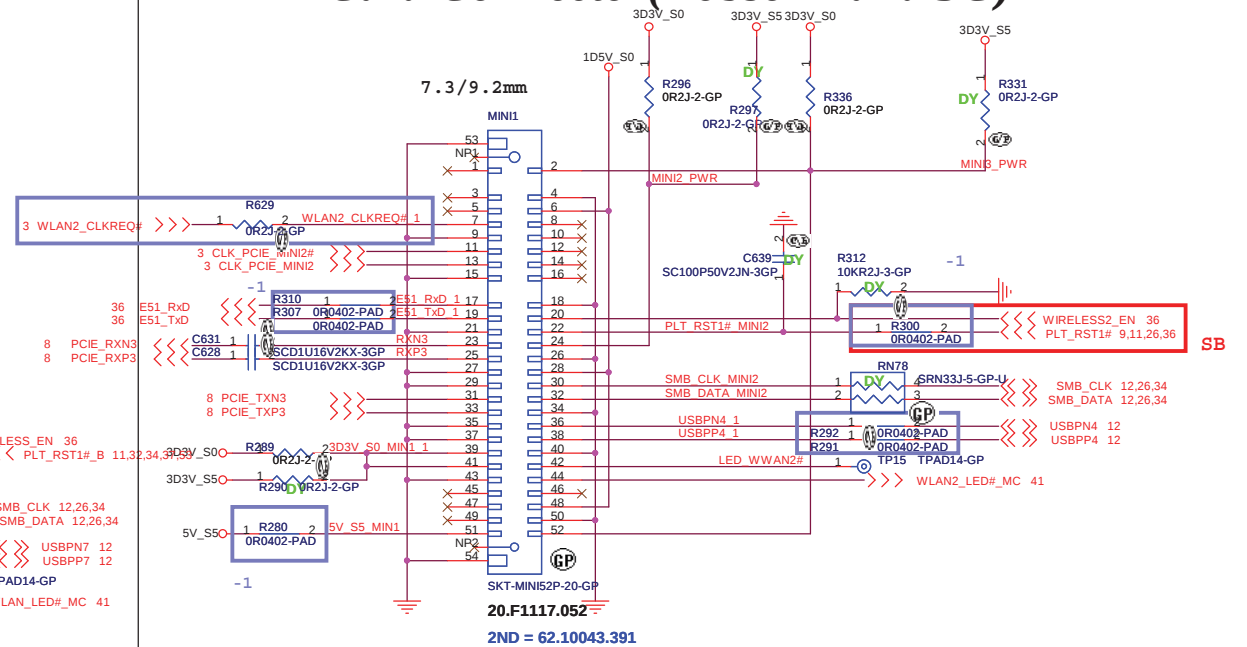
Rev

SB

Mini Card Connector(WLAN)

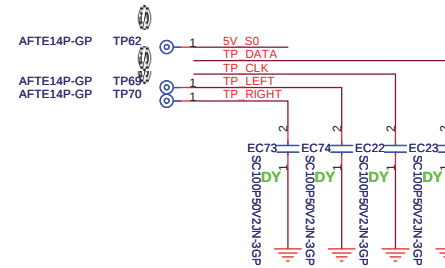
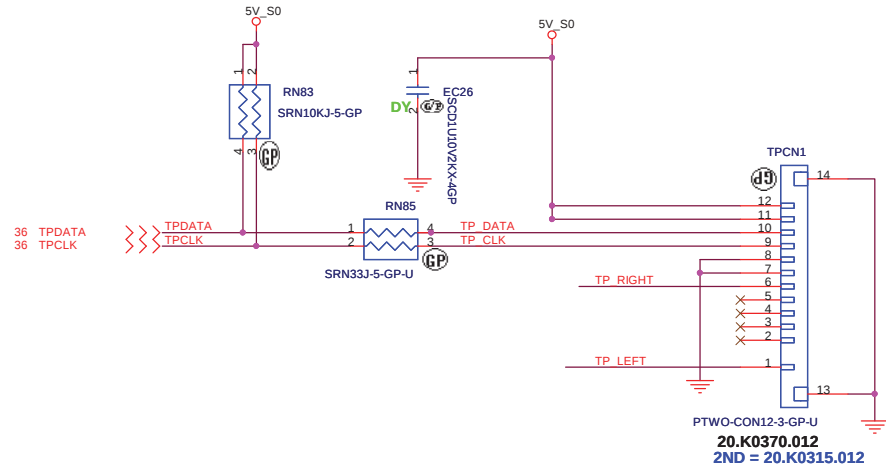


Mini Card Connector(Robson2 and 3G)

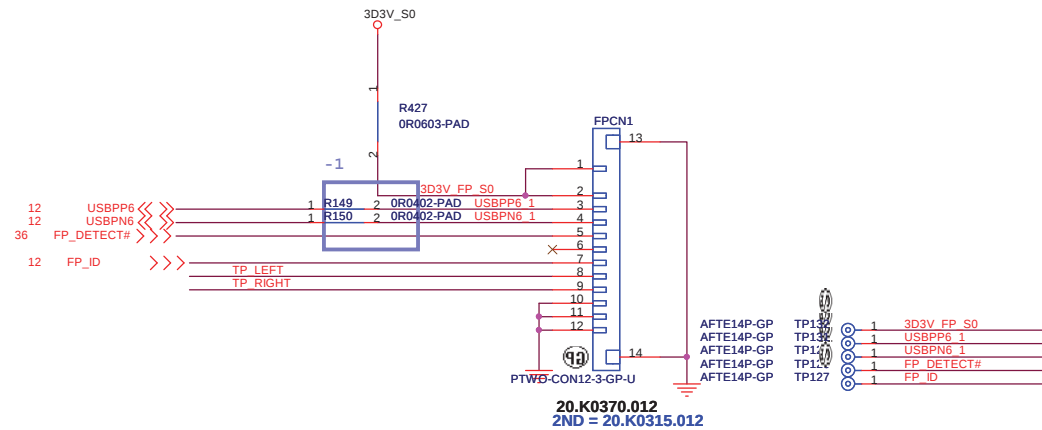




TOUCH PAD



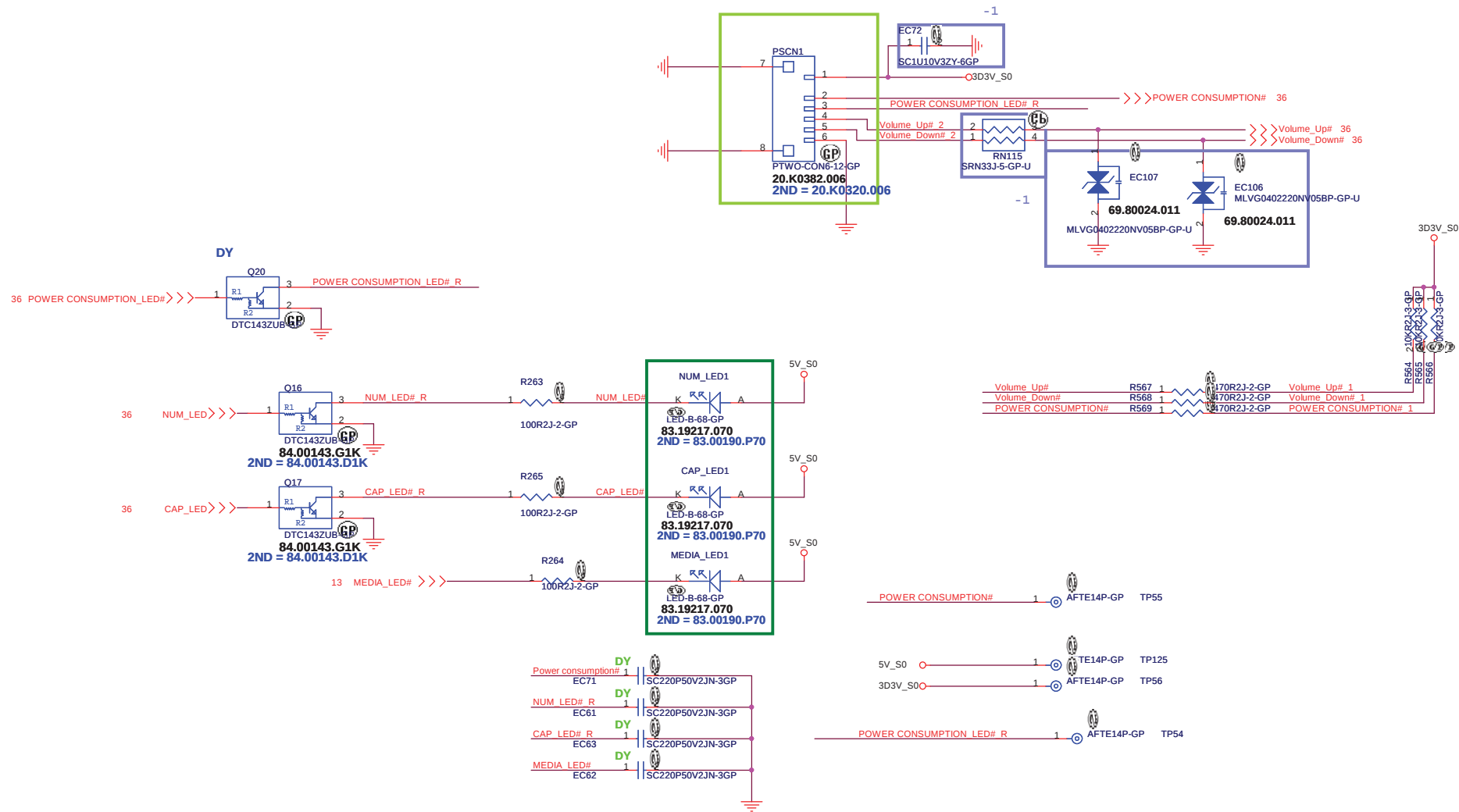
Finger printer



<Core Design>

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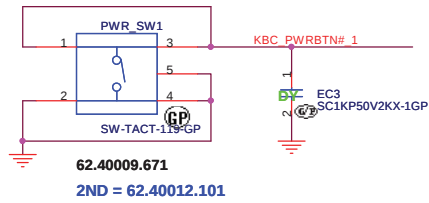
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Touch PAD/Finger printer		
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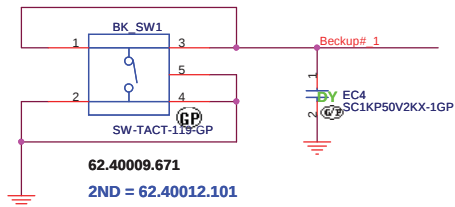
緯創資通 Wistron Corporation
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Title		
LAUNCH BOARD		
Size	Document Number	Rev
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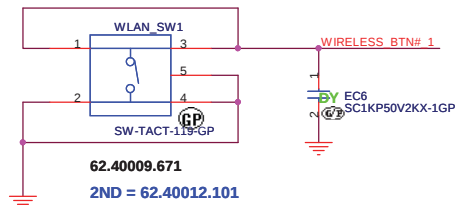
Power Button



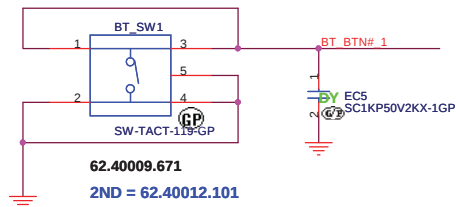
Beckup Button



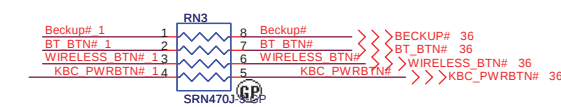
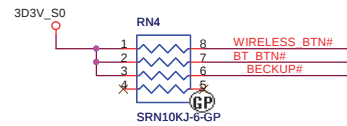
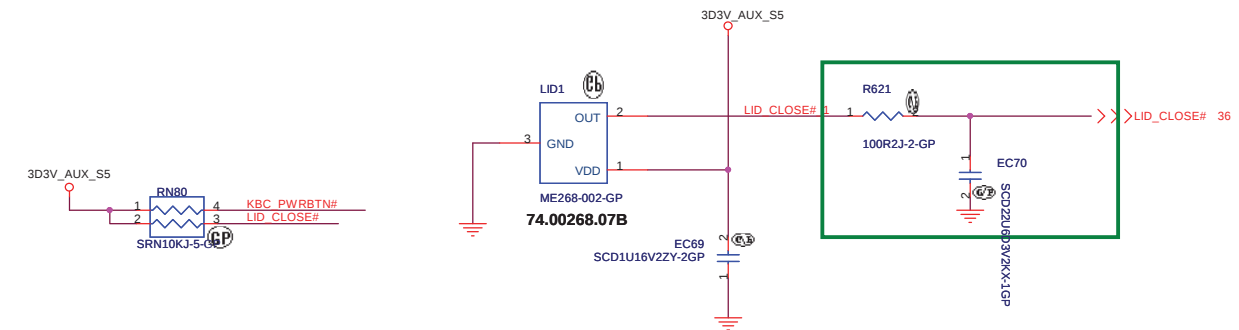
WIRELESS Button



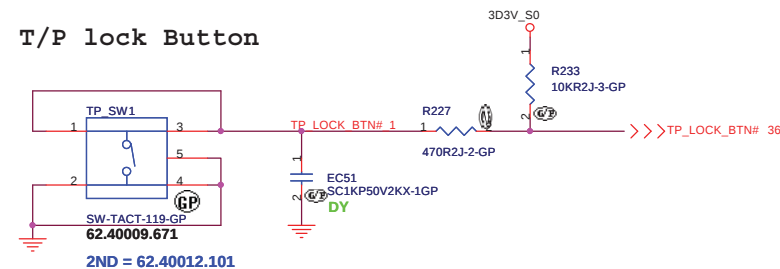
BT/3G Button



Cover Up Switch

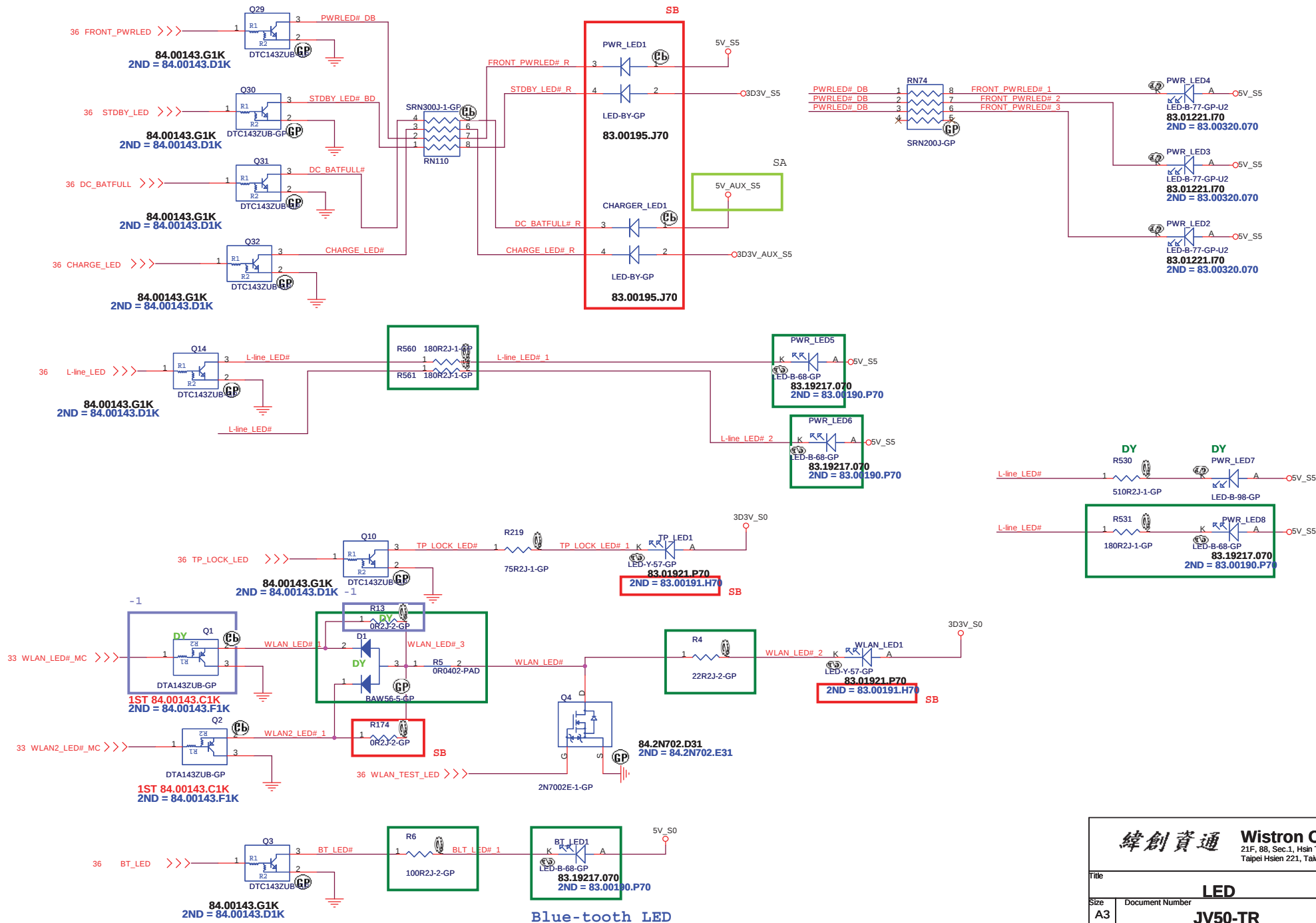


T/P lock Button



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Title			SWITCH
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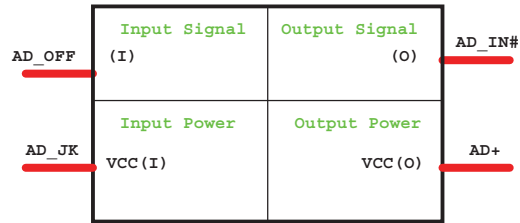




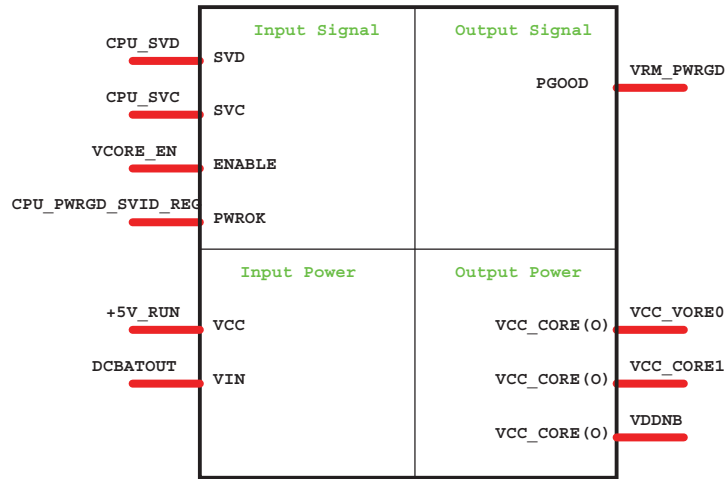
45 VRM_PWRGD>>>1R1201D1V_PWRGD 47



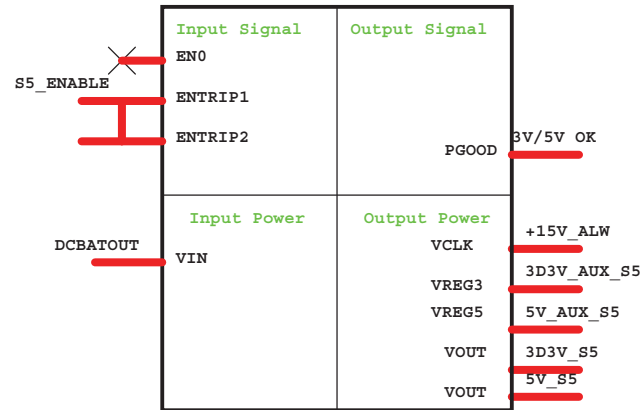
Adapter



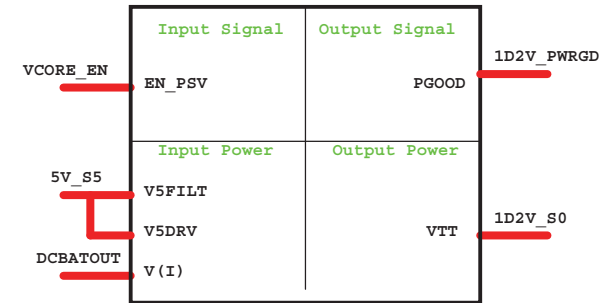
CPU_CORE ISL6265HRTZ



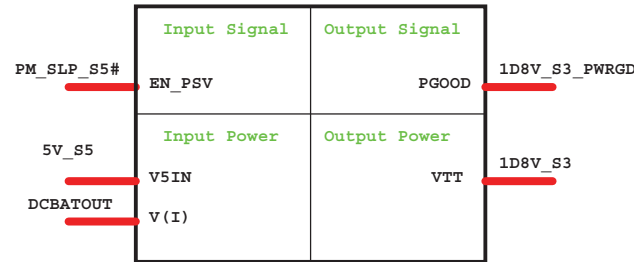
DCDC 5V/3D3V(RT8205A)



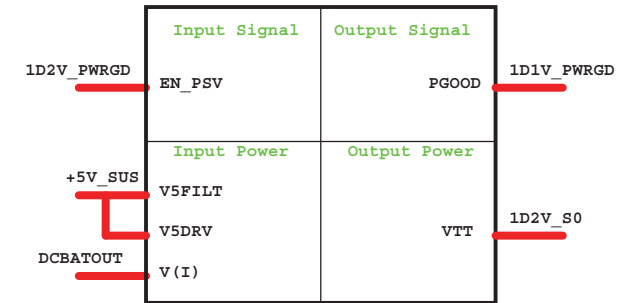
DCDC 1D2V(TPS51124)



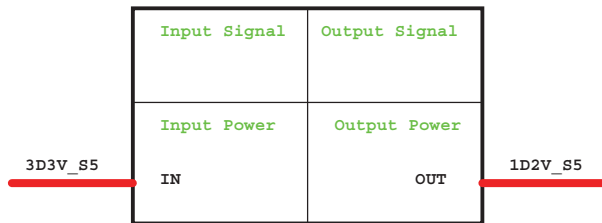
DCDC 1D8V(RT8209B)



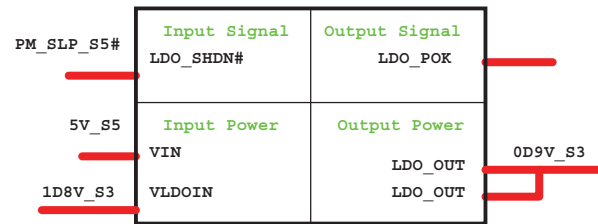
DCDC 1D1V(TPS51124)



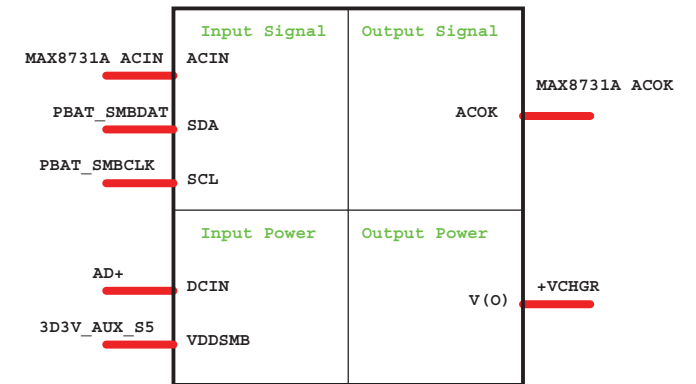
1D2V LDO G9161



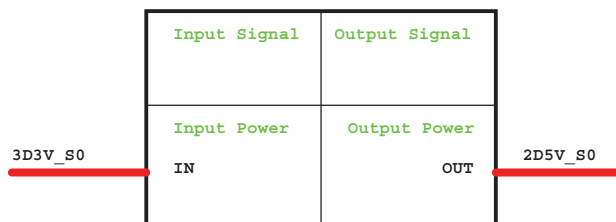
0D9V LDO RT9026



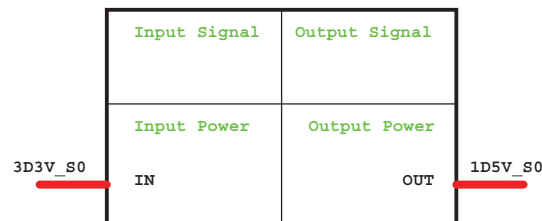
CHARGER MAX8731



2D5V LDO R9161



1D5V LDO G9571

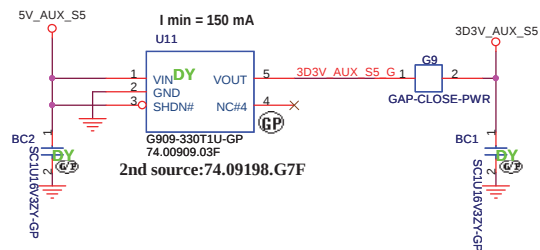


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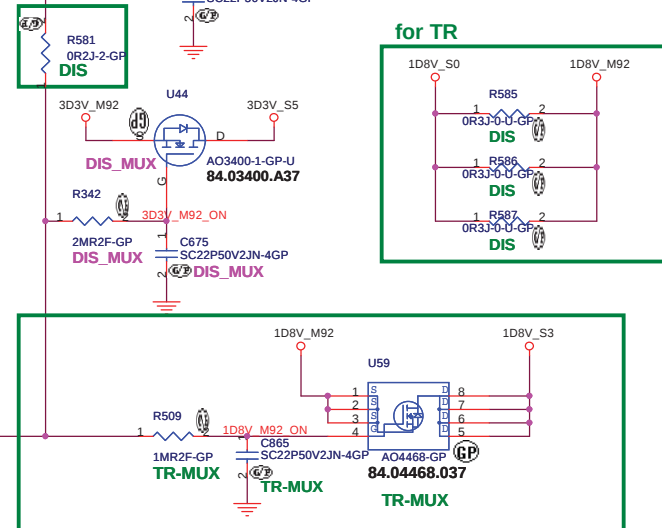
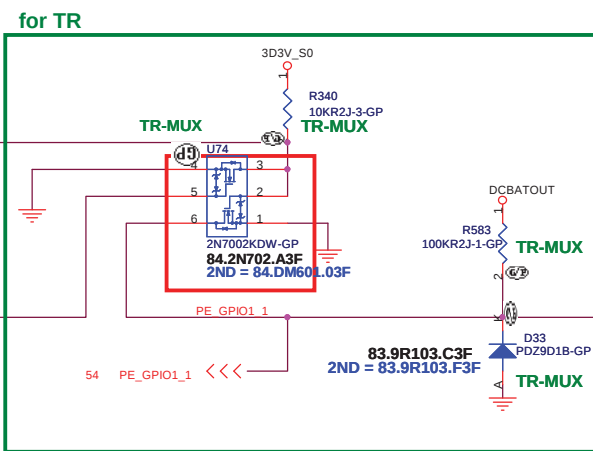
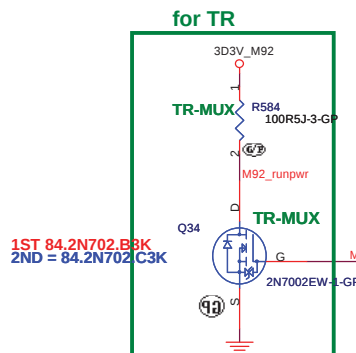
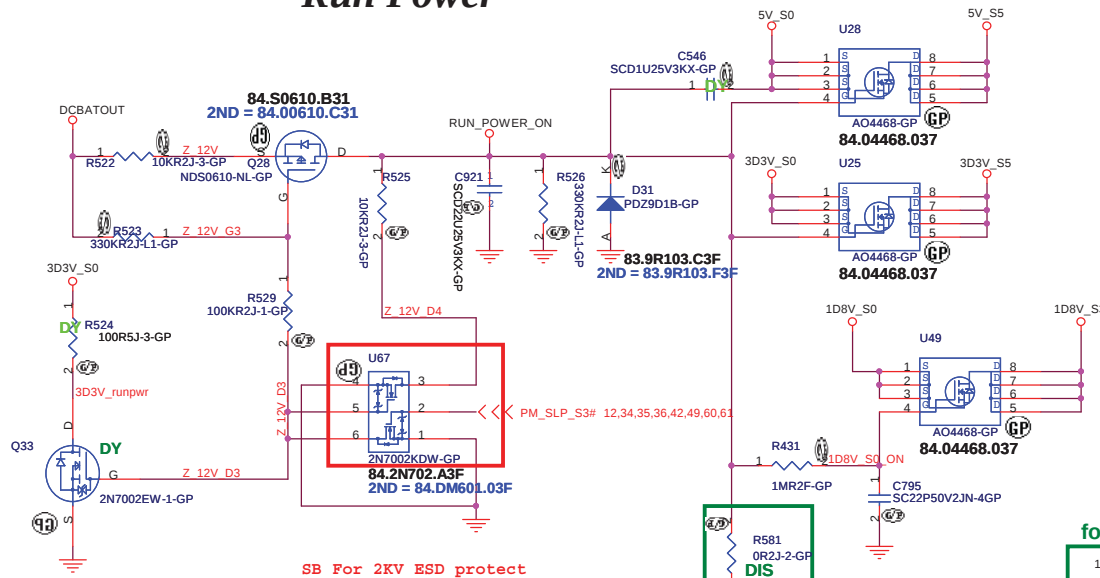
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Title			Power Block Diagram
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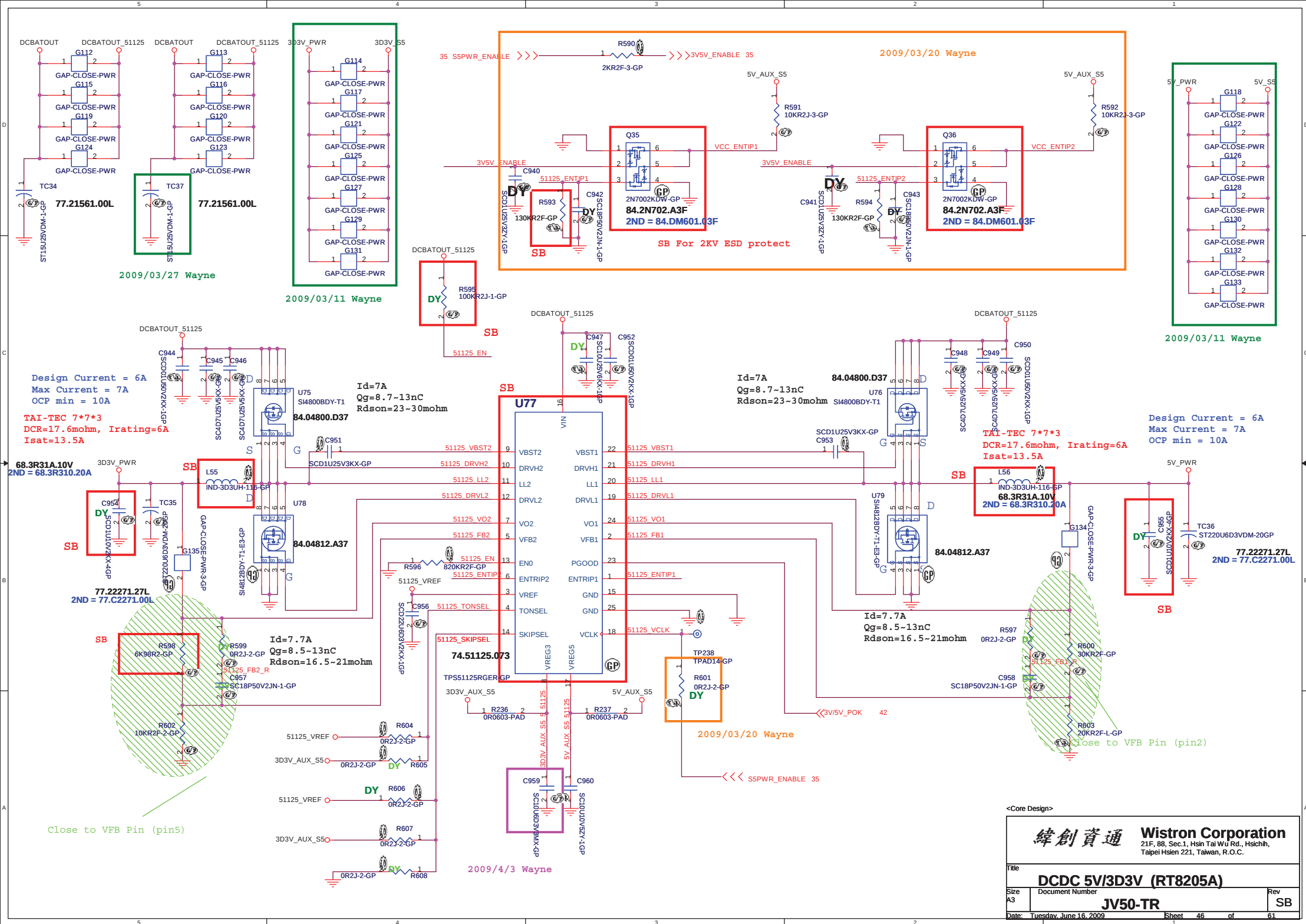
Aux Power 3D3V_AUX_S5

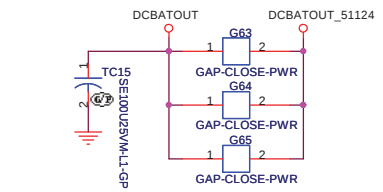


Run Power

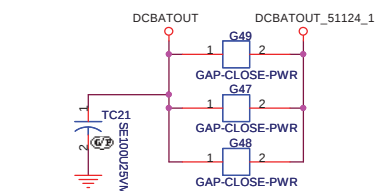








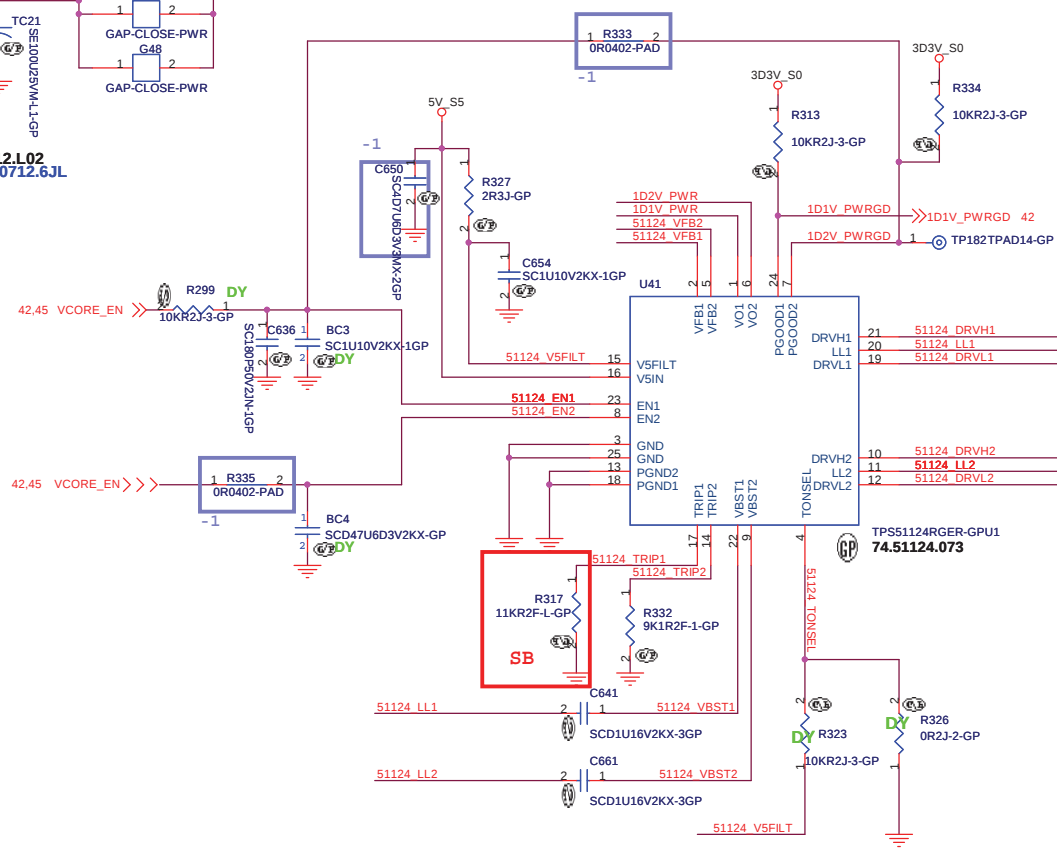
79.10712.1.02
2ND = 79.10712.6JL



79.10712.1.02
2ND = 79.10712.6JL

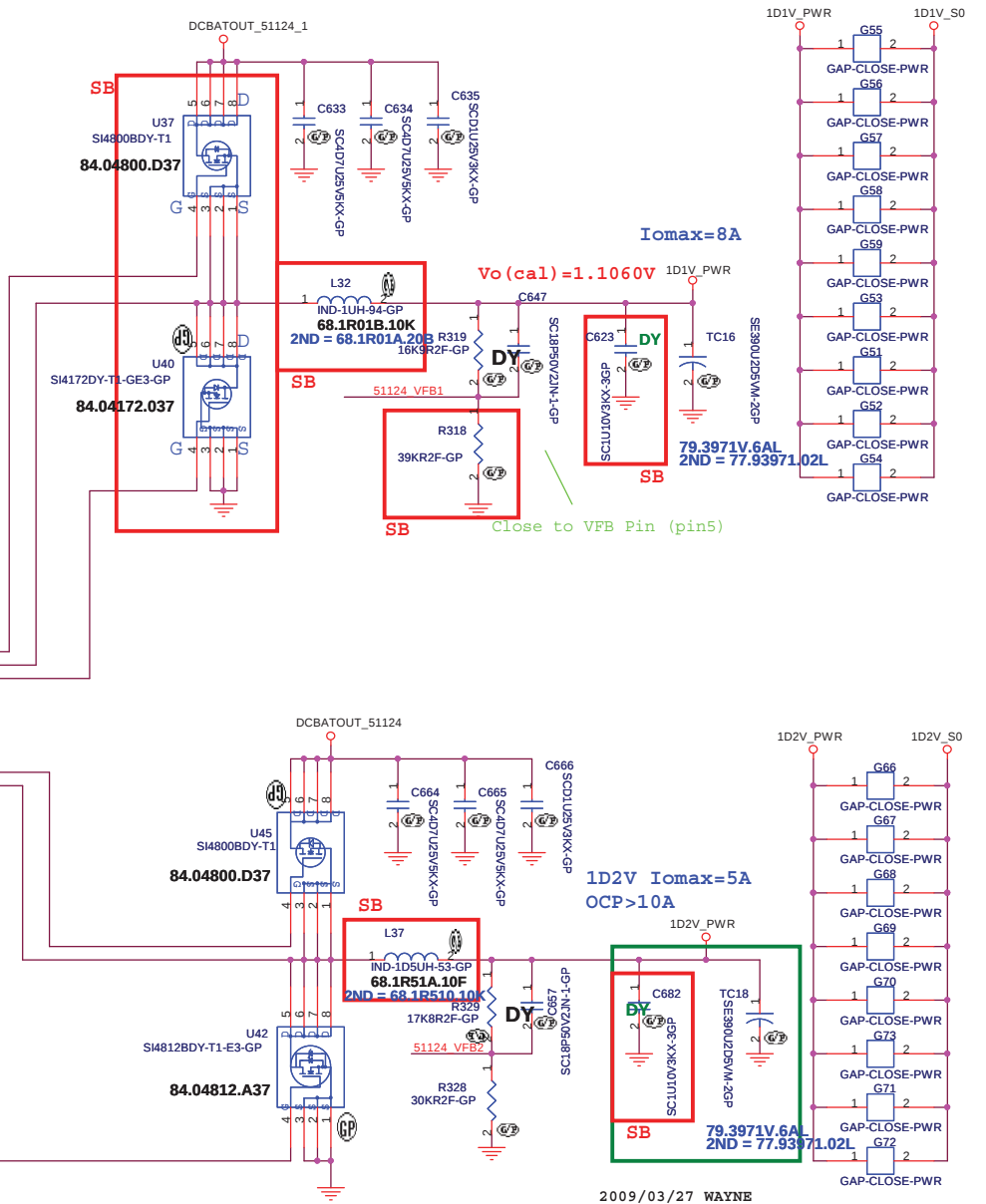
$$V_{trip} (mV) = R_{trip} (Kohm) * 10 (uA)$$

$$I_{ocp} = (V_{trip} / R_{dson}) + ((1 / (2 * L * f)) * ((V_{in} - V_{out}) * V_{out}) / V_{in})$$



	GND	OPEN	V5FILT
TONSEL	240k/CH1 300k/CH2	300k/CH1 360k/CH2	360k/CH1 420k/CH2

$V_{out} = 0.758V * (R1 + R2) / R2$ --> PWM mode
 $V_{out} = 0.764V * (R1 + R2) / R2$ --> Skip Mode



2009/03/27 WAYNE
C682 change to 1u10v for ESL

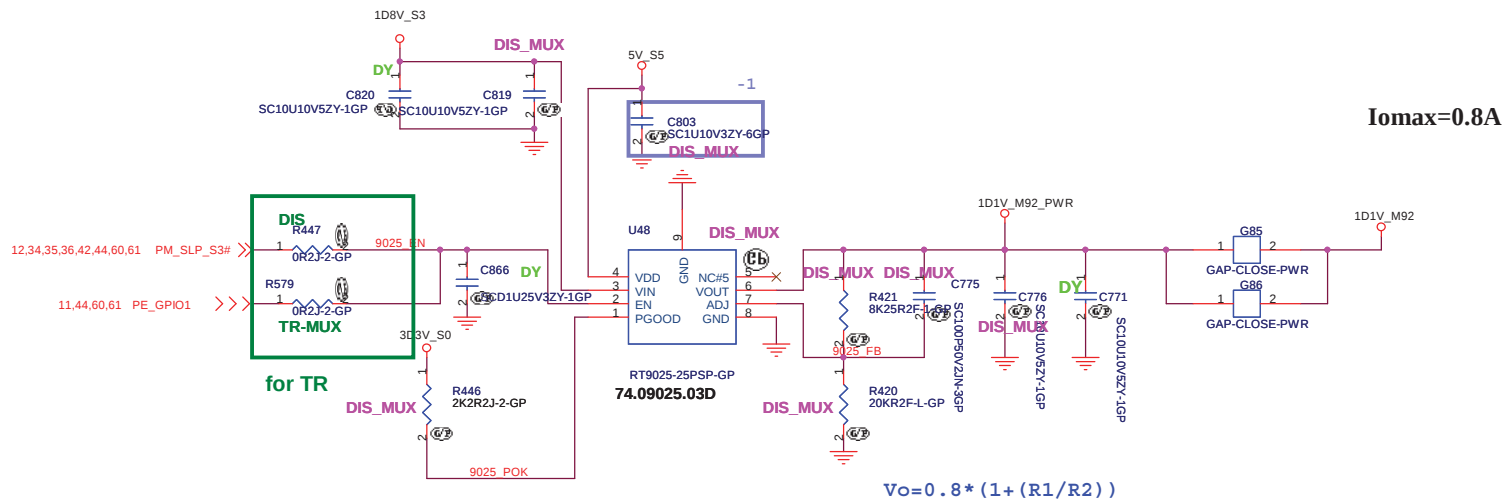
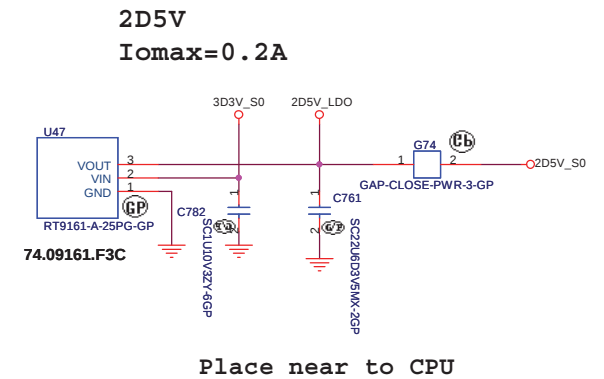
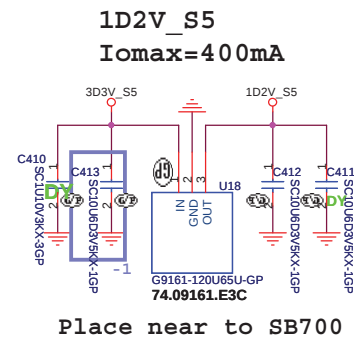
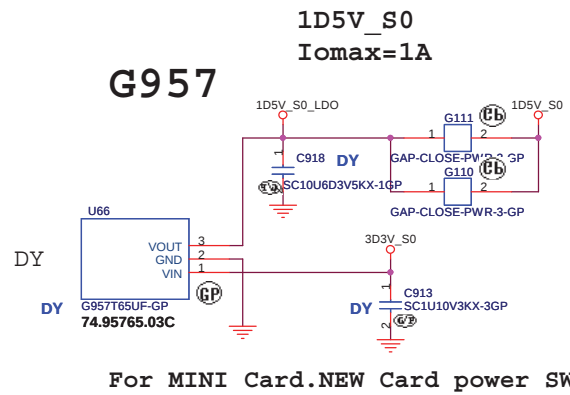
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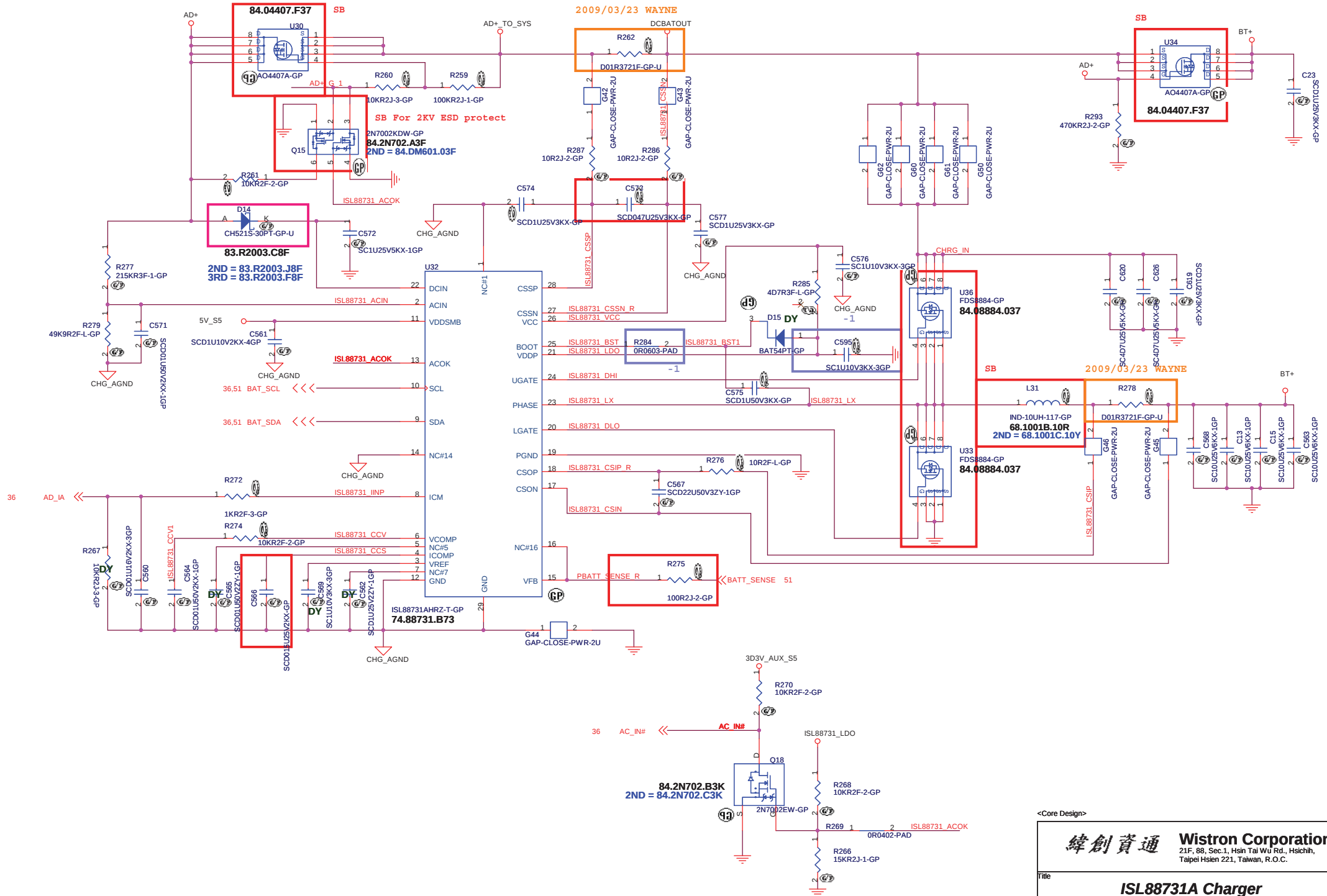
緯創資通 Wistron Corporation
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 Taipei Hsien 221, Taiwan, R.O.C.

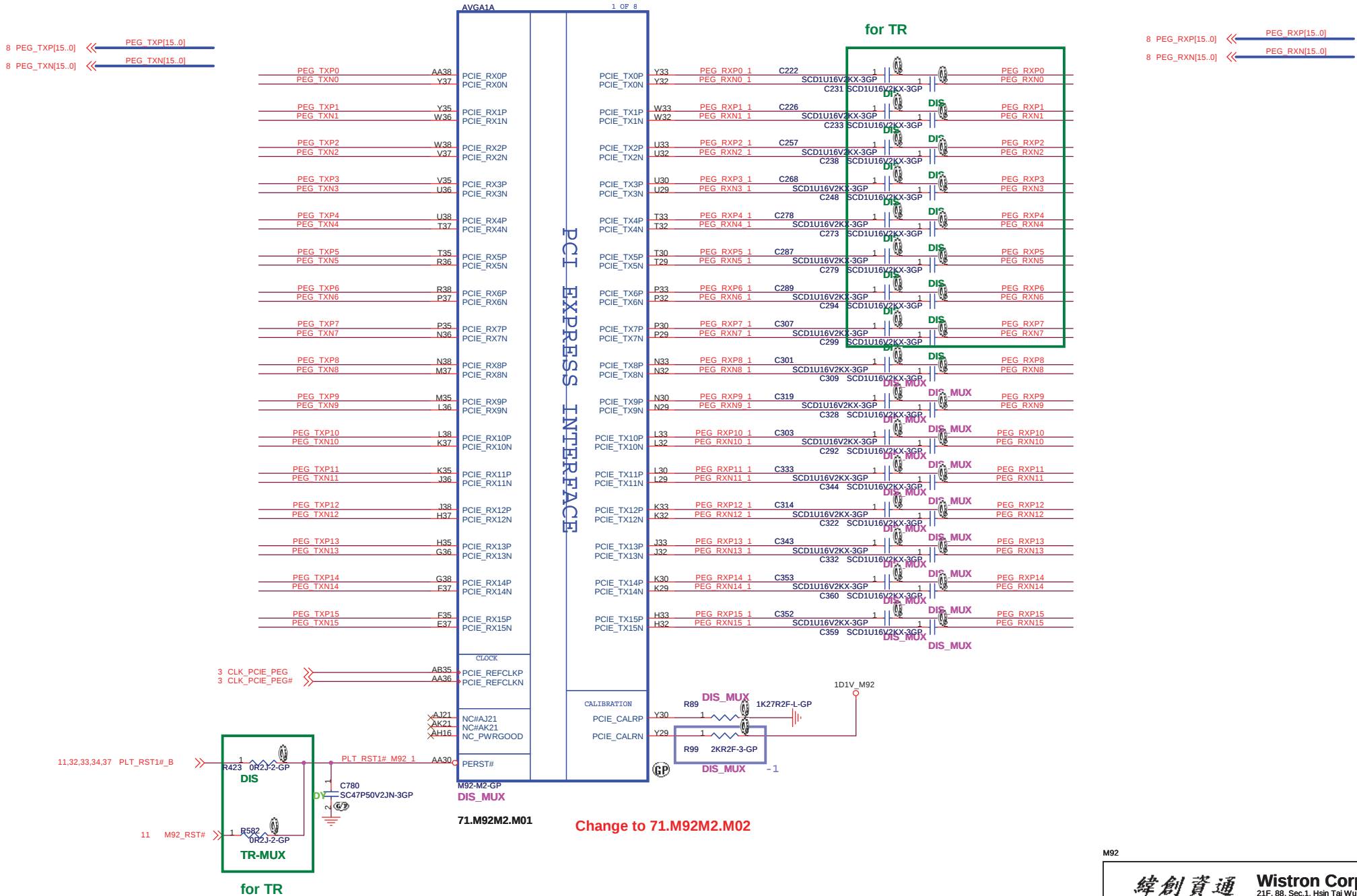
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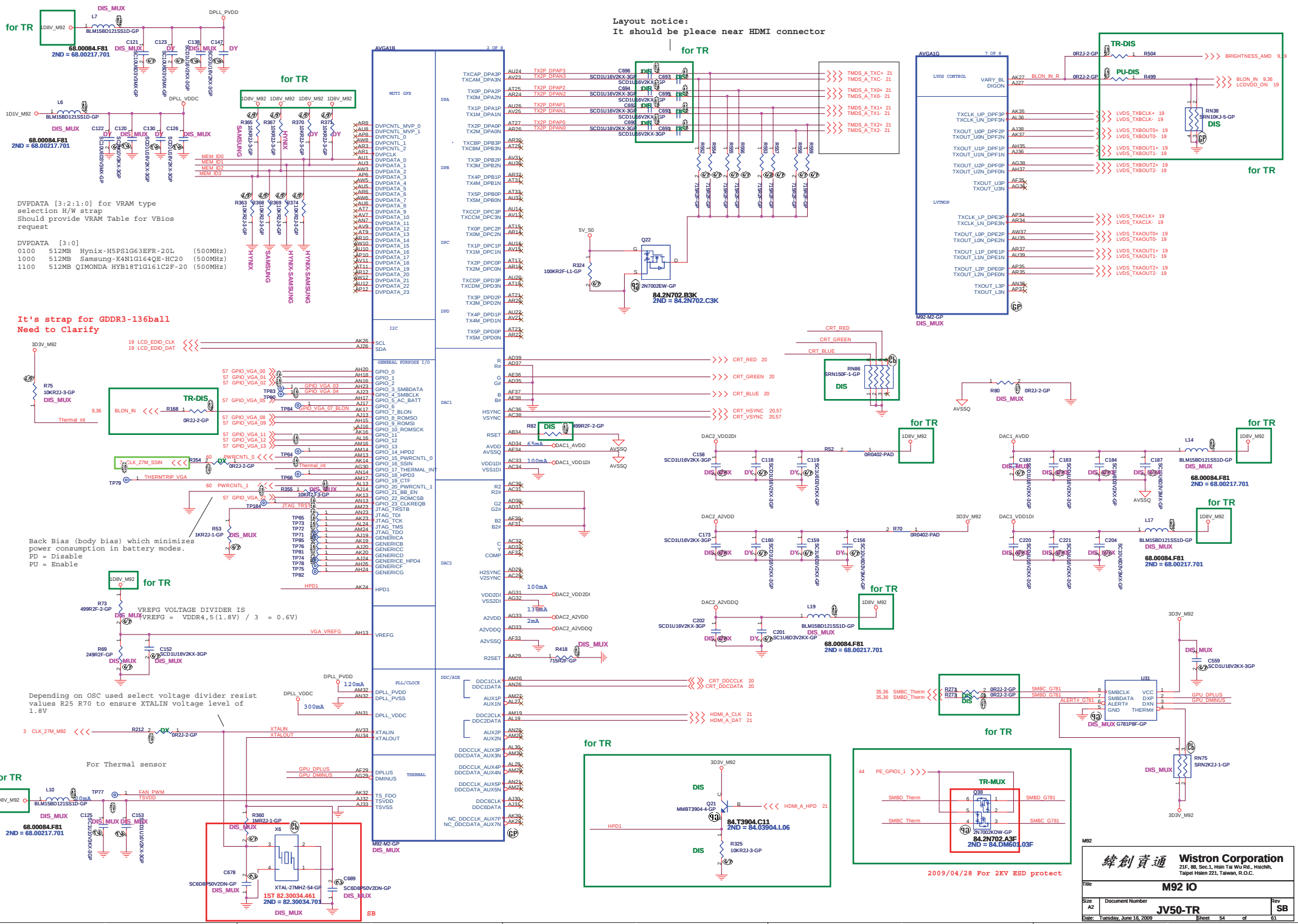
Size: A3 Document Number: **JV50-TR** Rev: **SB**

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Layout notice:
It should be placed near HDMI connector

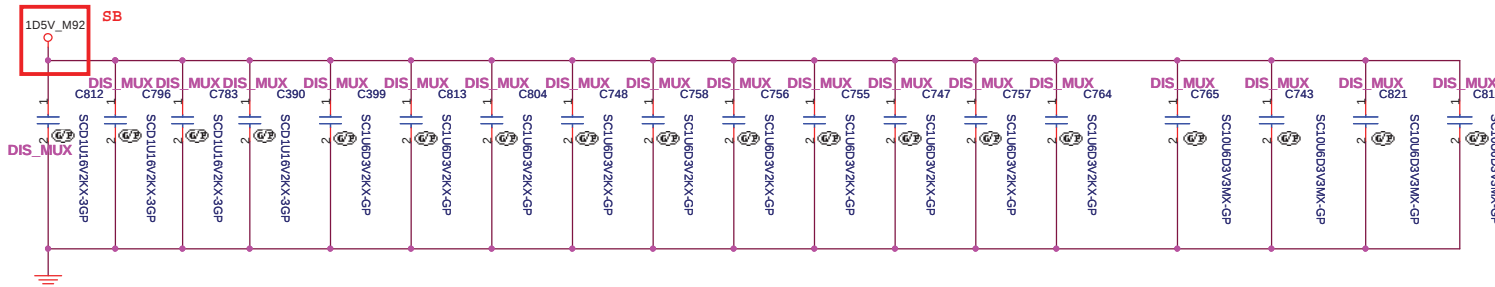
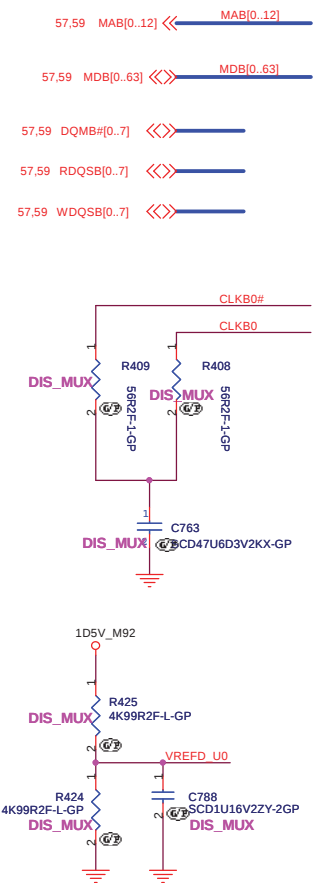
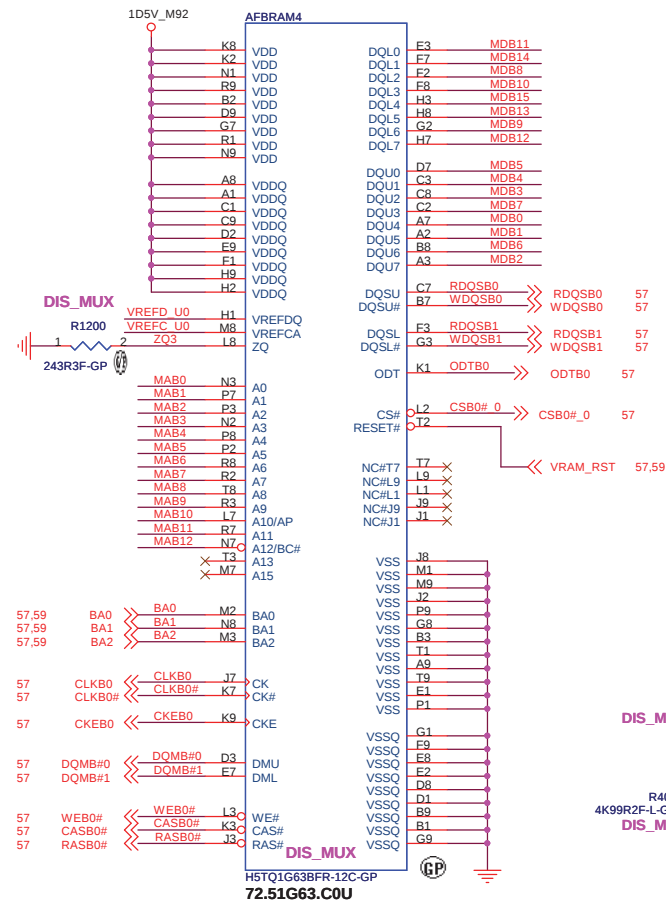
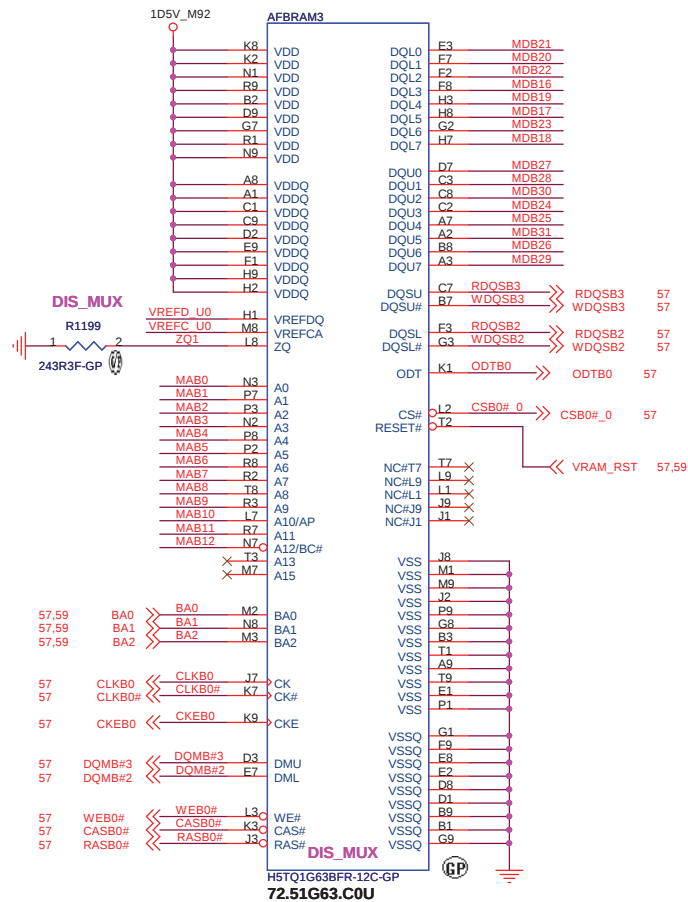
It's strap for GDDR3-136ball
Need to Clarify

Back Bias (body bias) which minimizes power consumption in battery modes.
PD = Disable
PU = Enable

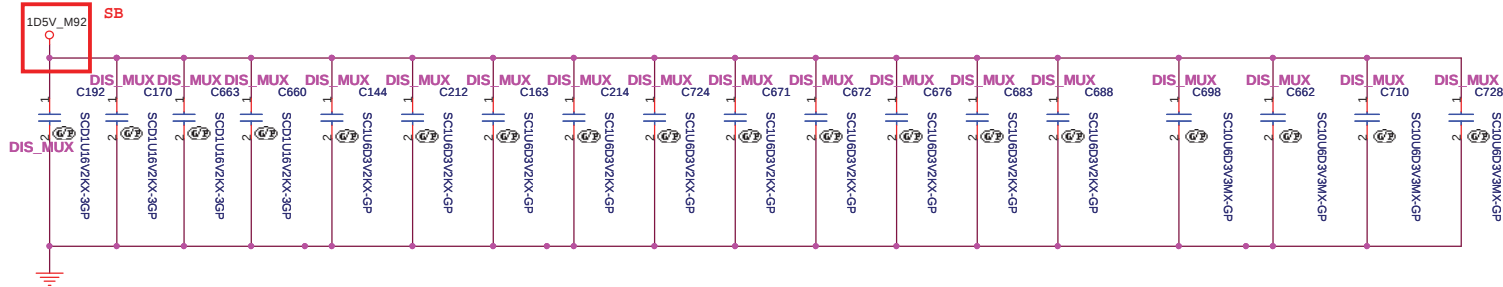
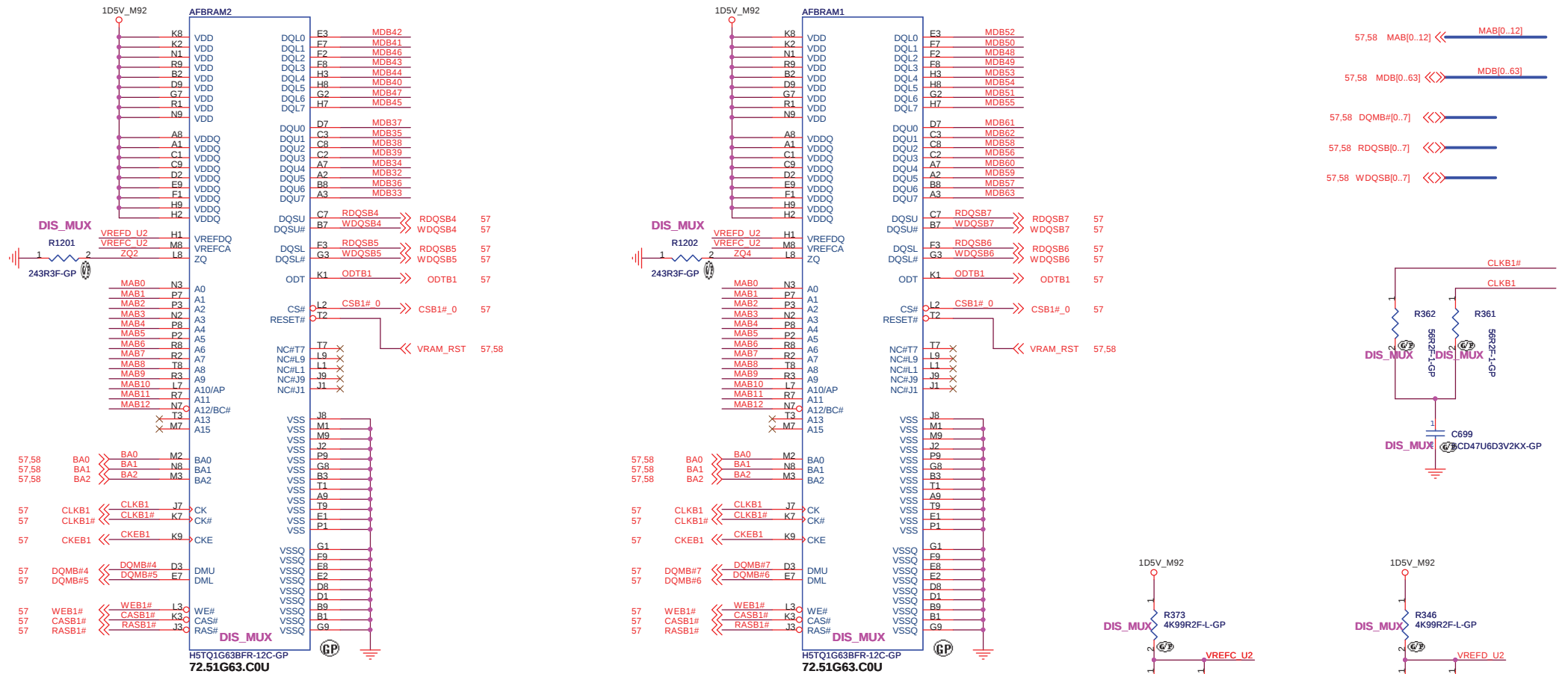
Depending on OSC used select voltage divider resist values R25 R70 to ensure XTALIN voltage level of 1.8V

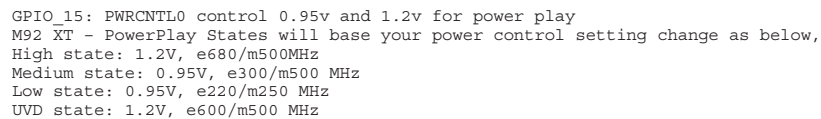
For Thermal sensor

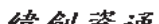
DDR3



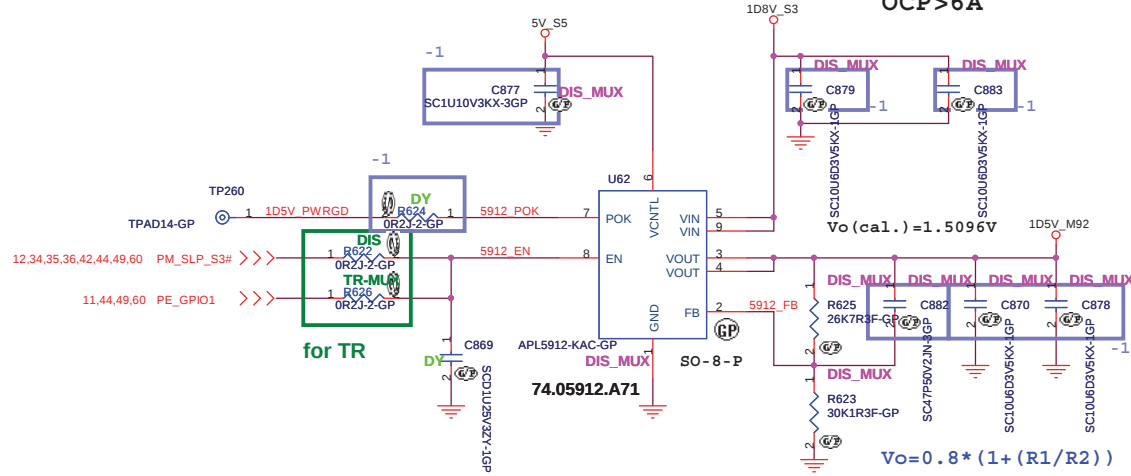
DDR3





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RT8202A VGA CORE			
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1D5V_S0
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OCP>6A



<Core Design>

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Taipei Hsien 221, Taiwan, R.O.C.

Title		APL5912 1D5V VRAM POWER	
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